



US 20200408594A1

(19) **United States**

(12) **Patent Application Publication**

Omote et al.

(10) **Pub. No.: US 2020/0408594 A1**

(43) **Pub. Date: Dec. 31, 2020**

(54) **VIBRATION DETECTING DEVICE**

H05K 5/00 (2006.01)

H05K 1/18 (2006.01)

(71) Applicants: **Kabushiki Kaisha Toshiba**, Tokyo (JP); **Toshiba Electronic Devices & Storage Corporation**, Tokyo (JP)

(52) **U.S. Cl.**

CPC **G01H 17/00** (2013.01); **H05K 7/1427** (2013.01); **H05K 1/0277** (2013.01); **H05K 1/144** (2013.01); **H05K 2201/10151** (2013.01); **H05K 1/181** (2013.01); **H05K 2201/10189** (2013.01); **H05K 2201/10113** (2013.01); **H05K 2201/042** (2013.01); **H05K 5/0026** (2013.01)

(72) Inventors: **Hirofumi Omote**, Adachi Tokyo (JP); **Hiroshi Ota**, Misato Saitama (JP); **Ryoji Ninomiya**, Kunitachi Tokyo (JP)

(21) Appl. No.: **16/784,399**

(57) **ABSTRACT**

(22) Filed: **Feb. 7, 2020**

According to one embodiment, a vibration detecting device includes a housing, a vibration sensor, a circuit board, a flexible wiring member, and an elastic member. The vibration sensor is accommodated in the housing. The circuit board is accommodated in the housing, and is provided with a first electric component configured to process a detection signal of the vibration sensor. The wiring member electrically connects the vibration sensor and the circuit board to each other. The elastic member contains a polymer material, and is accommodated in the housing as being in contact with the housing and the circuit board, and being detachable from the housing. The circuit board is held by the housing through the elastic member.

(30) **Foreign Application Priority Data**

Jun. 28, 2019 (JP) 2019-122088

Publication Classification

(51) **Int. Cl.**

G01H 17/00 (2006.01)

H05K 7/14 (2006.01)

H05K 1/02 (2006.01)

H05K 1/14 (2006.01)

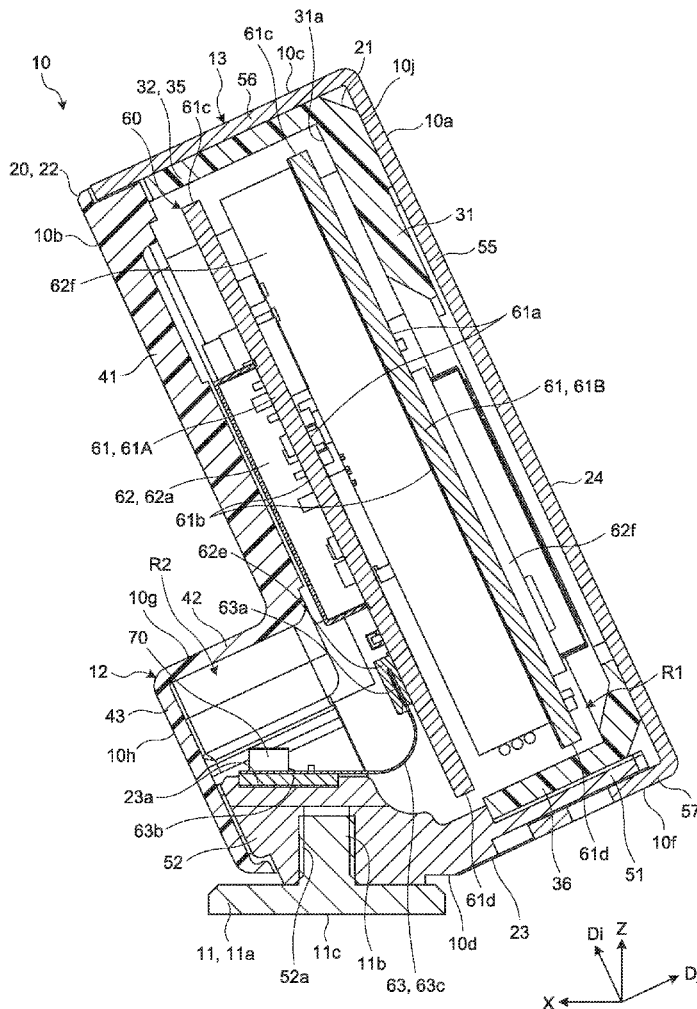


FIG. 1

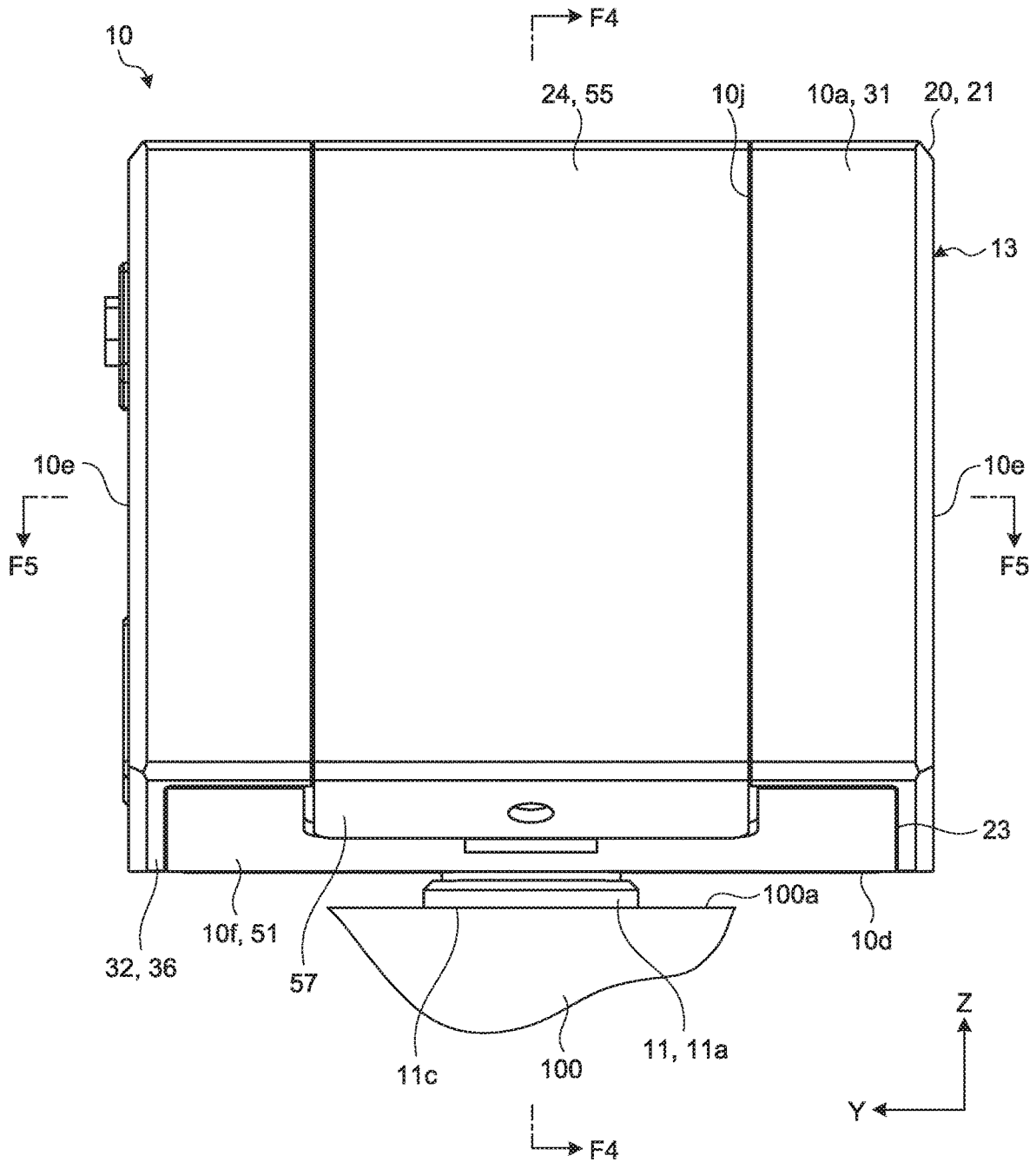


FIG.2

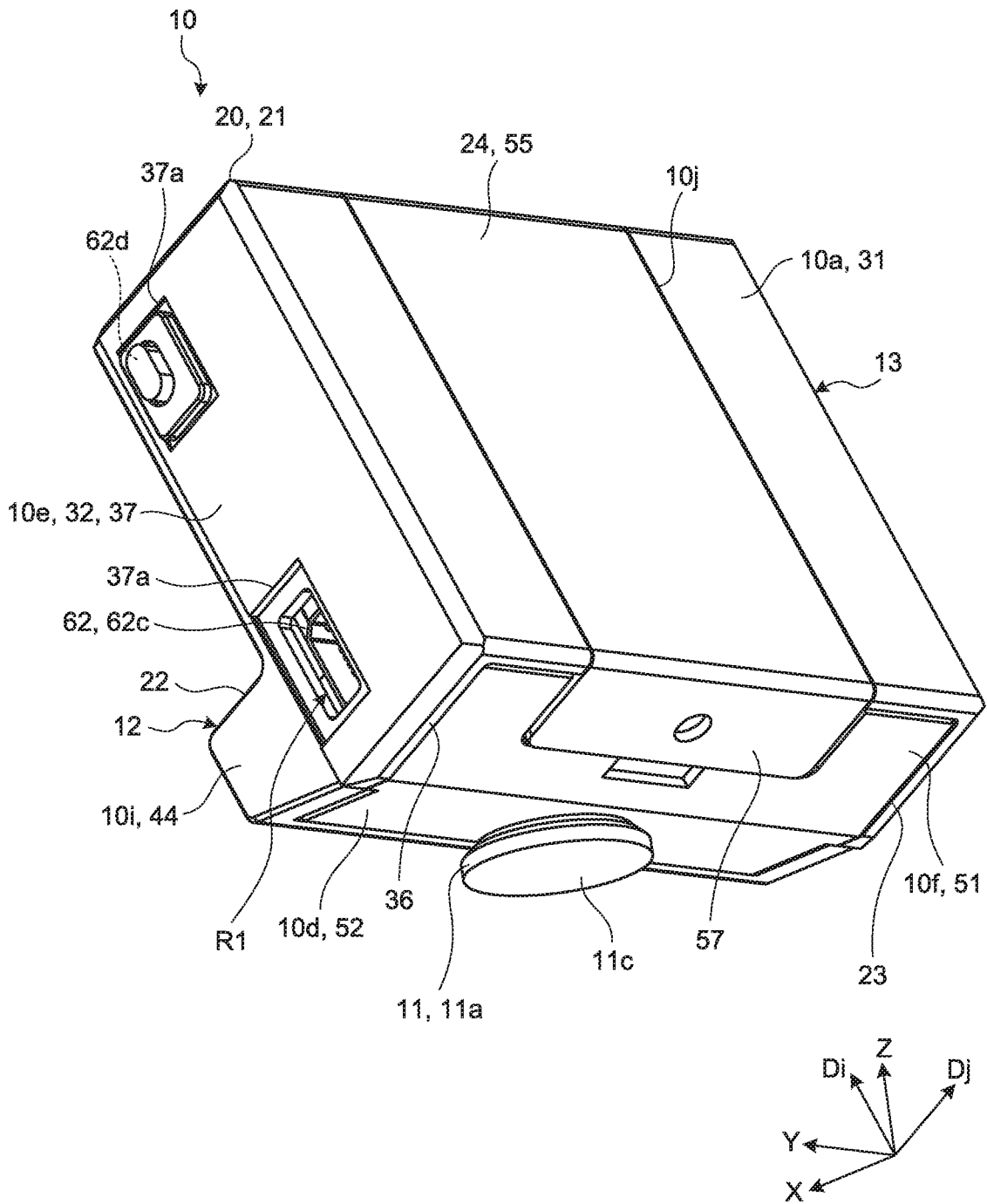


FIG.3

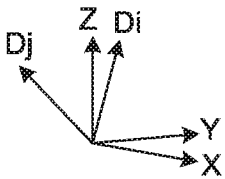
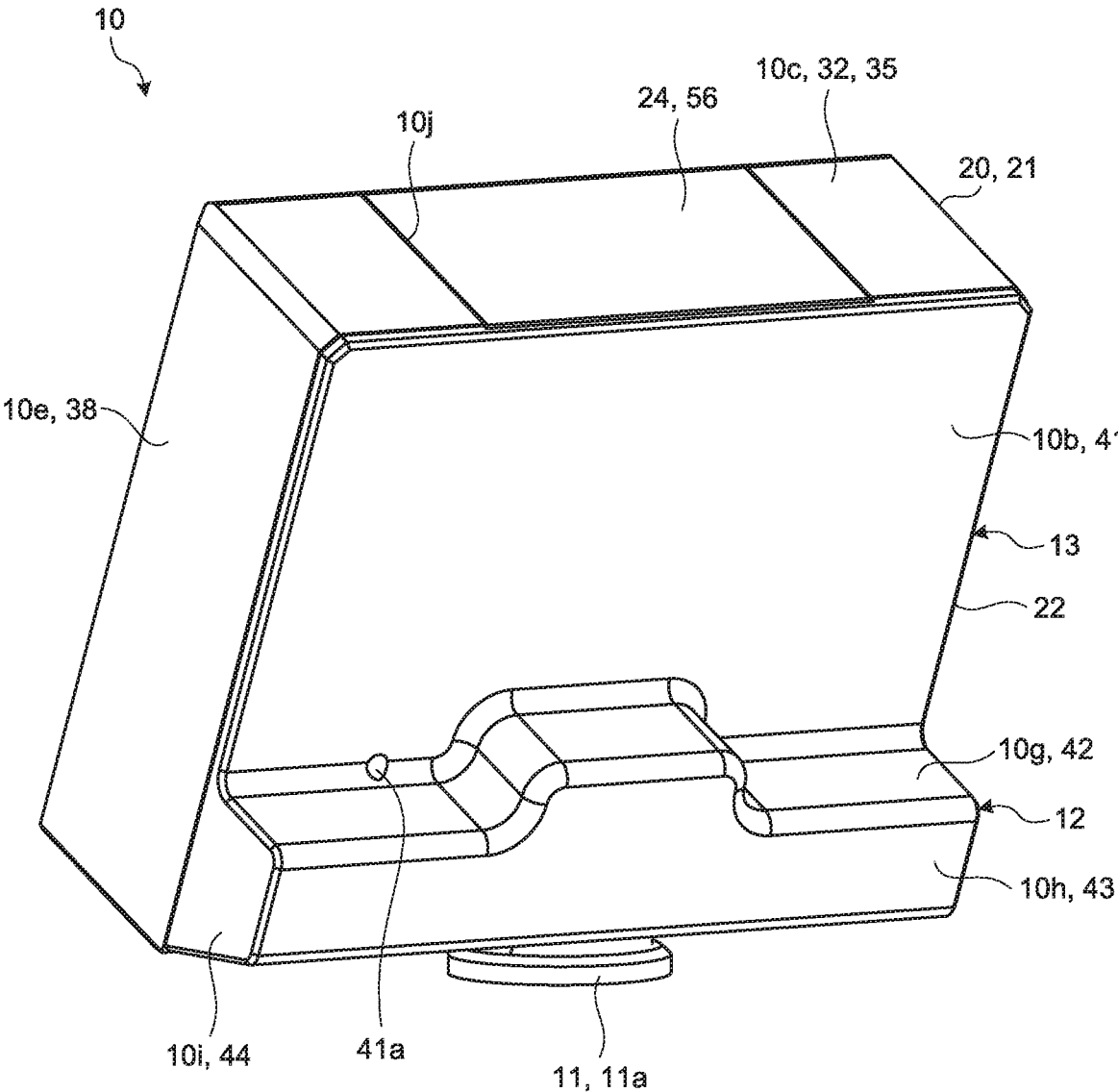


FIG.4

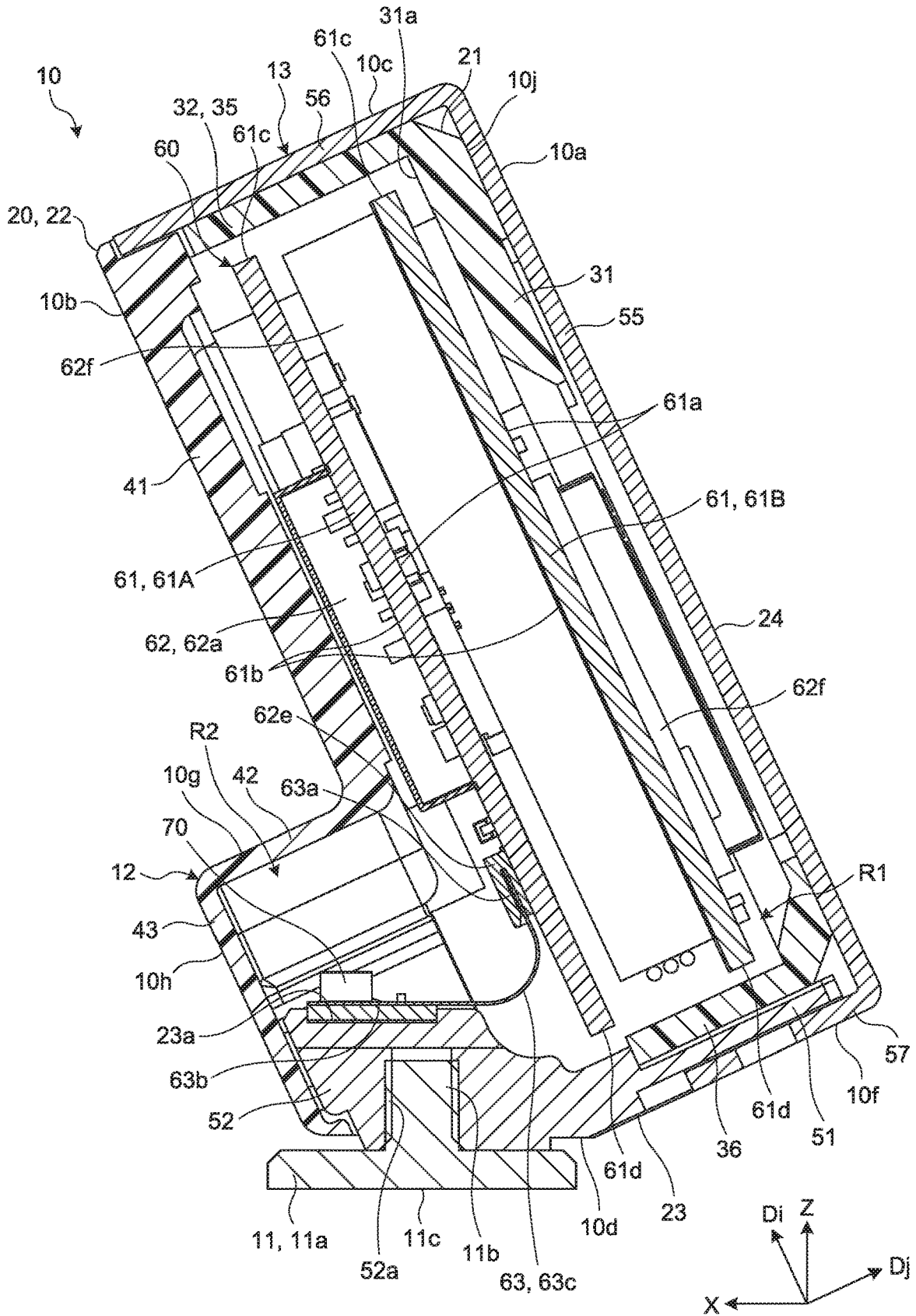


FIG.5

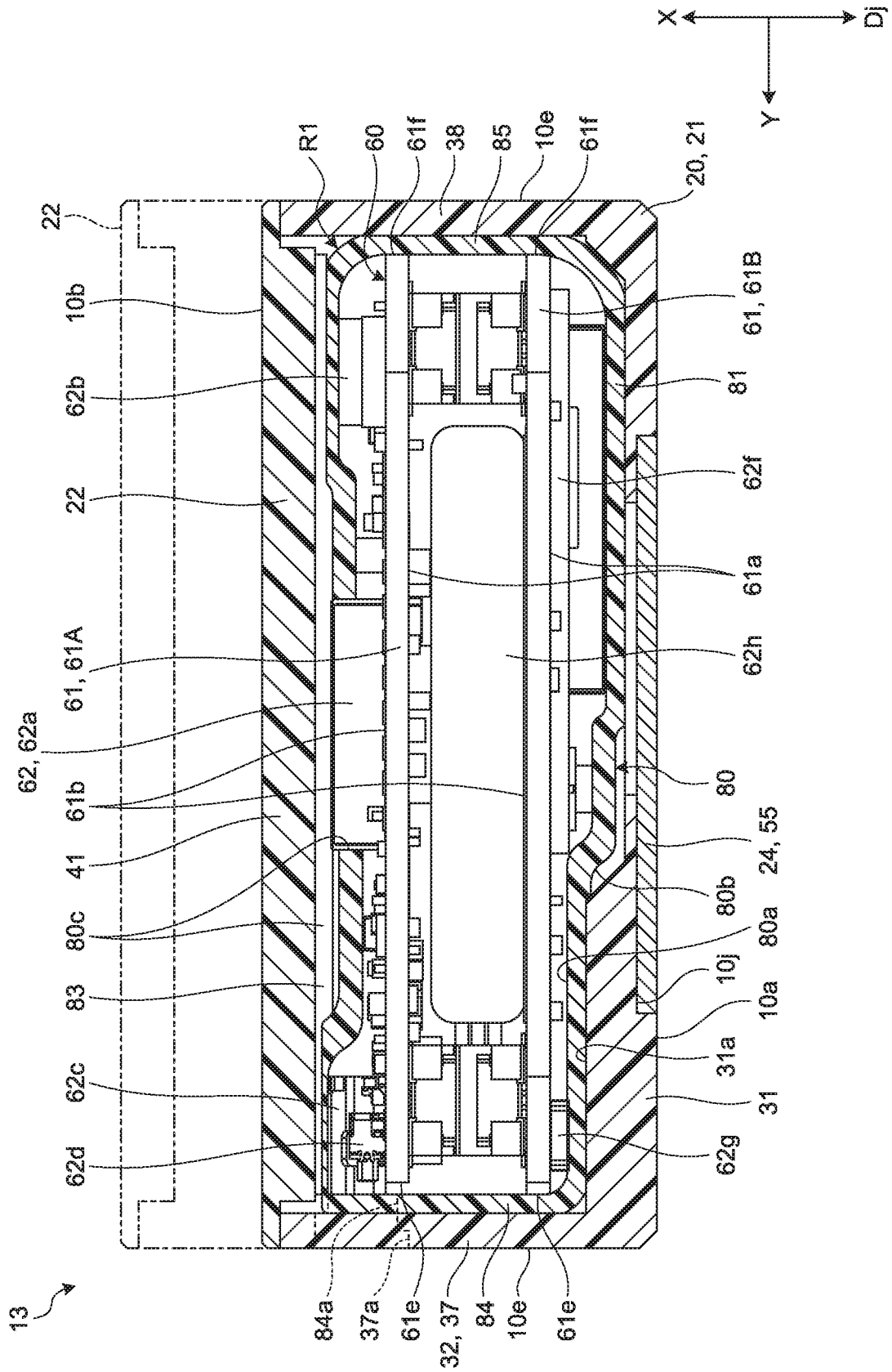


FIG.6

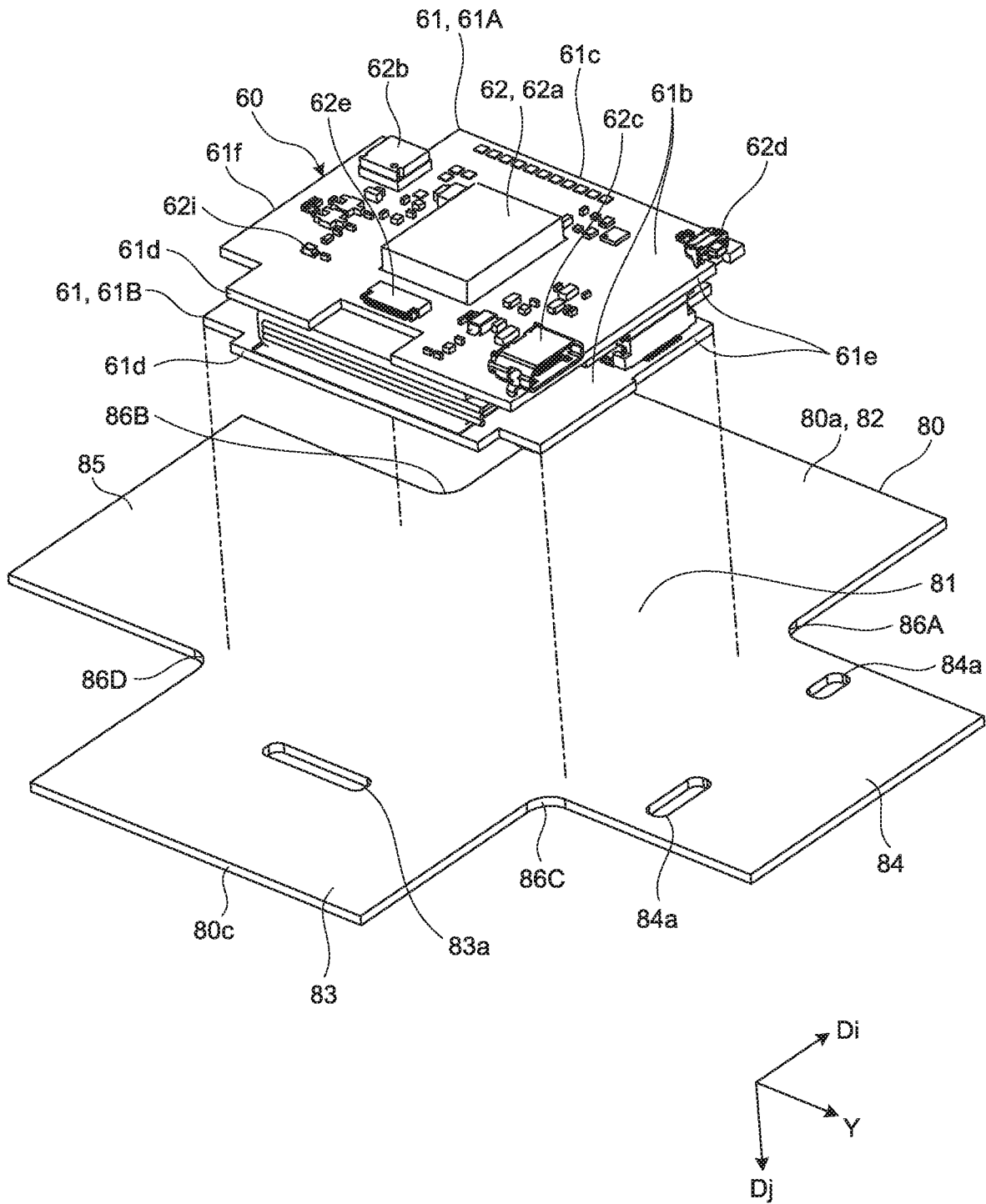


FIG. 7

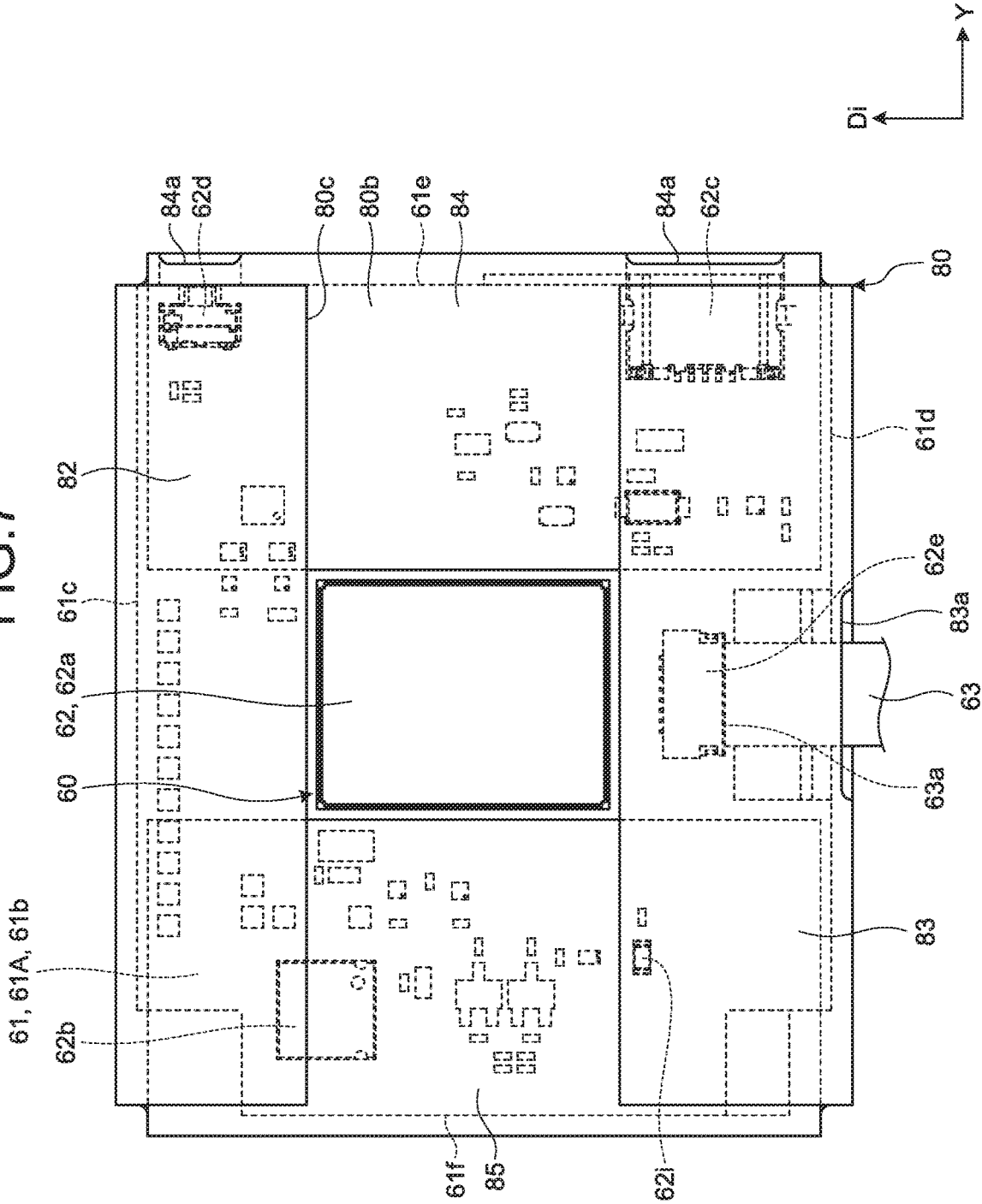
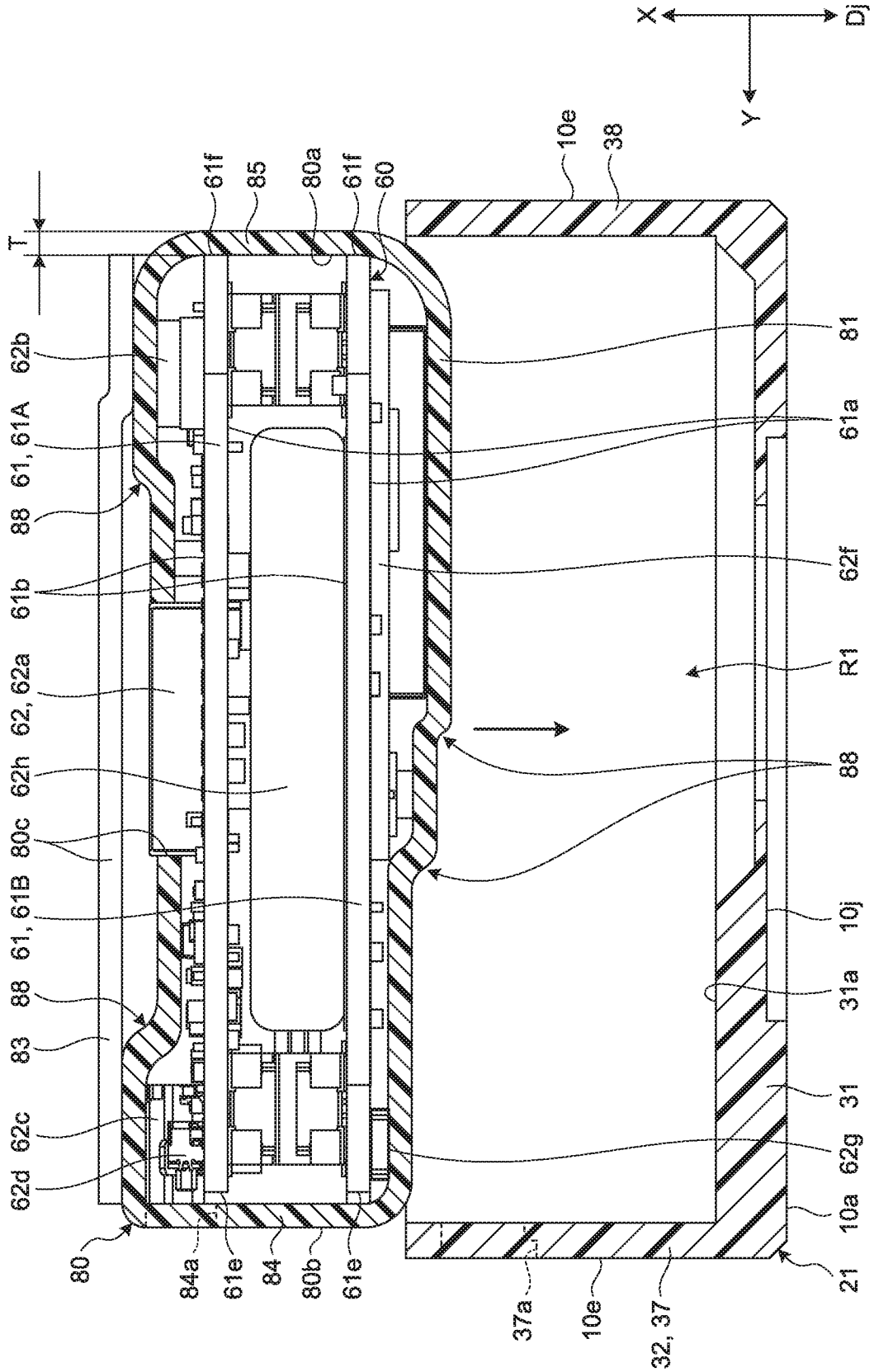


FIG.8



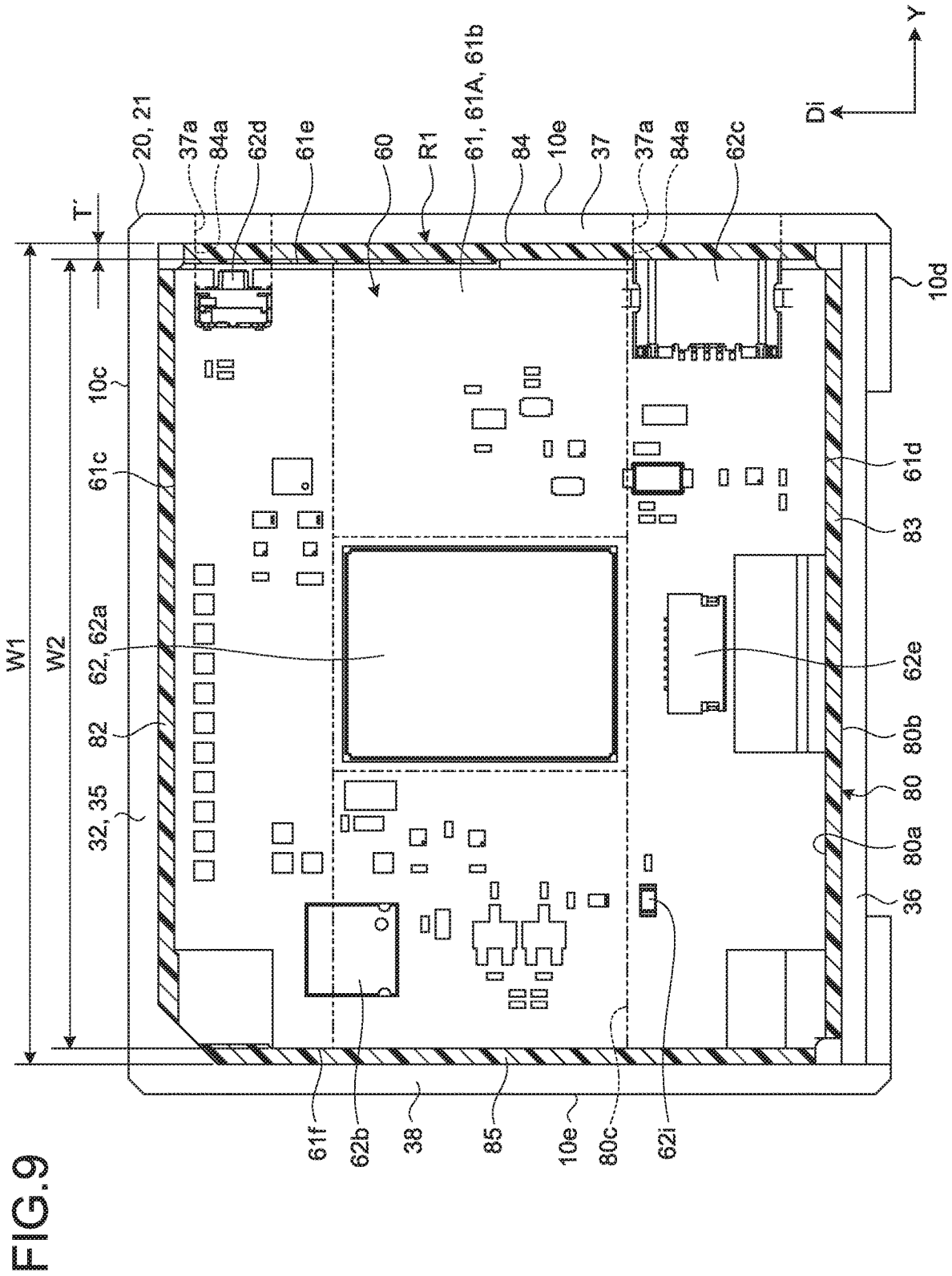


FIG. 9

FIG. 10

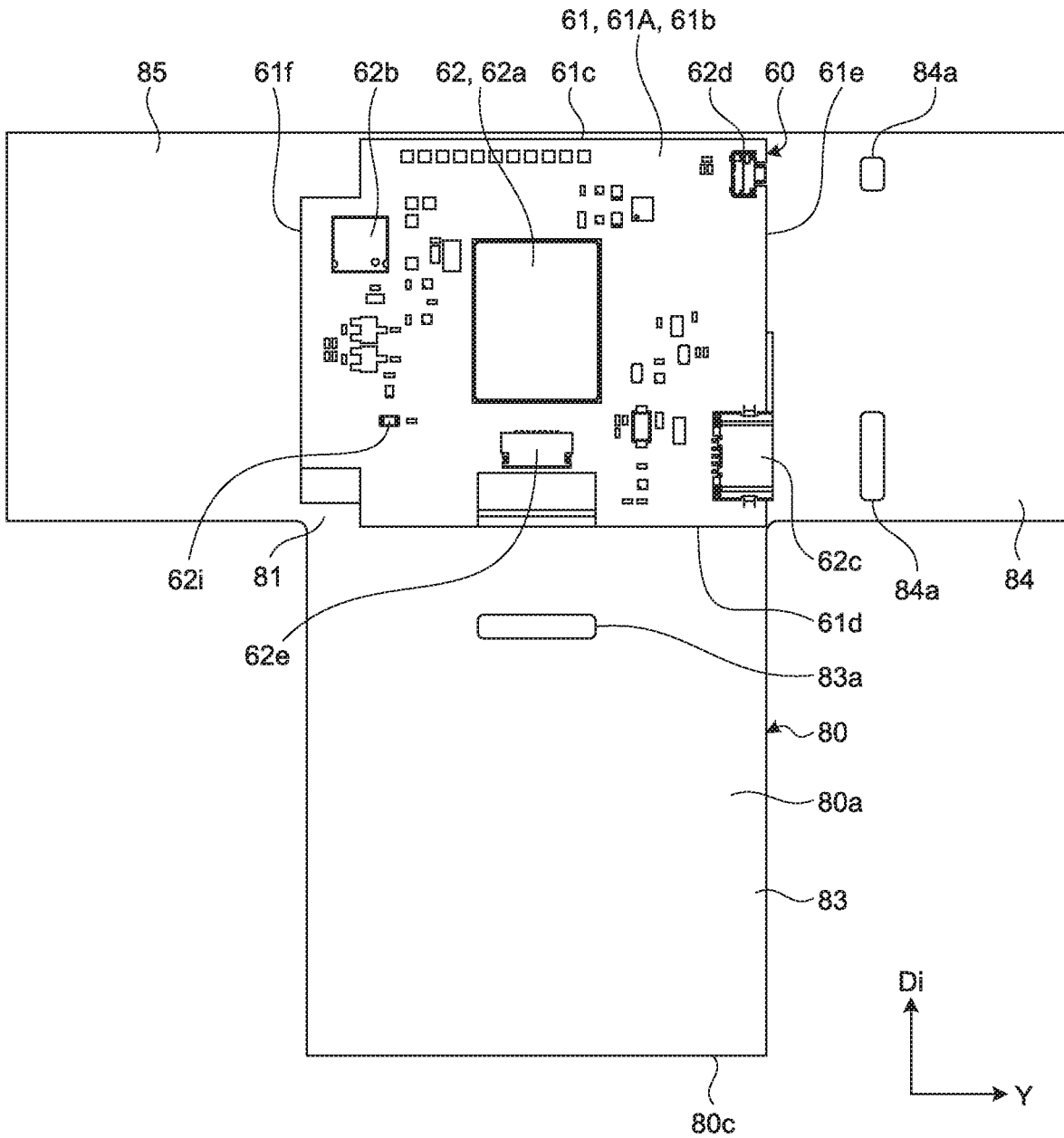


FIG. 11

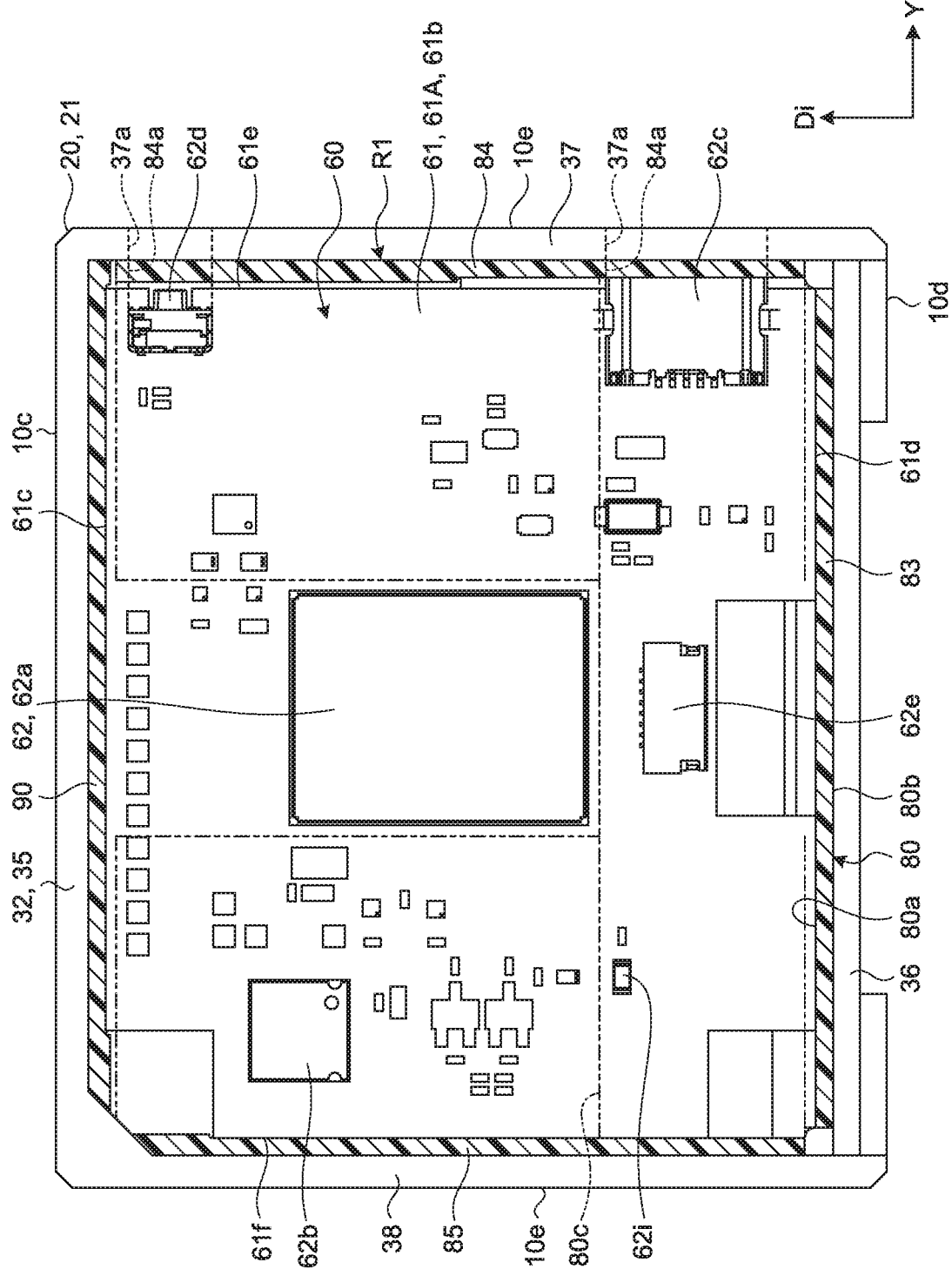


FIG.12

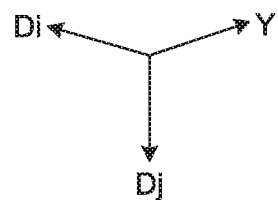
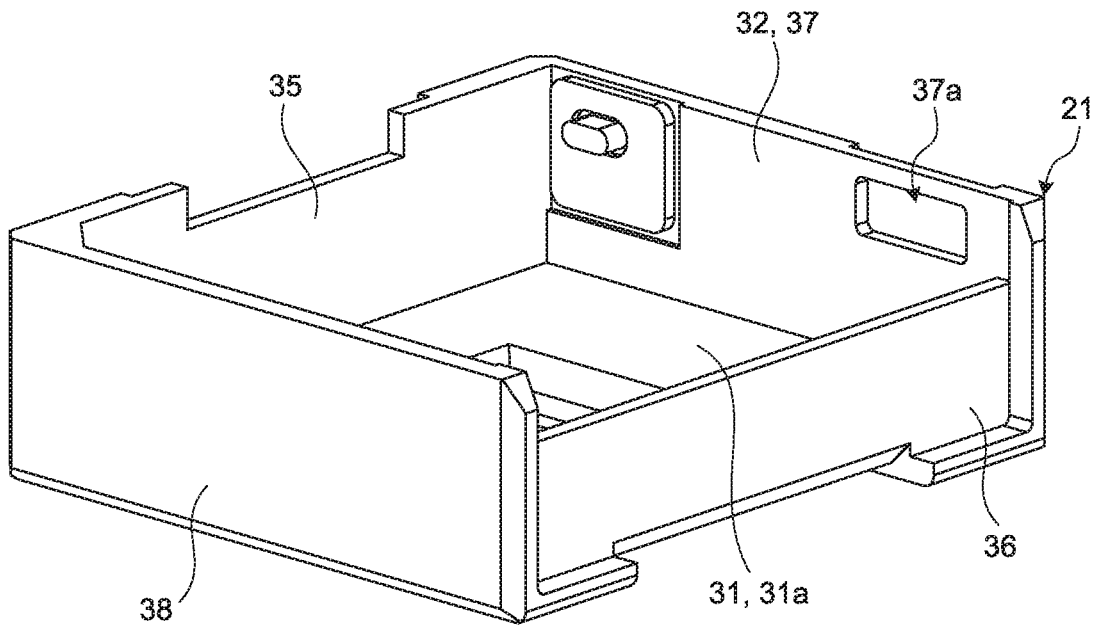
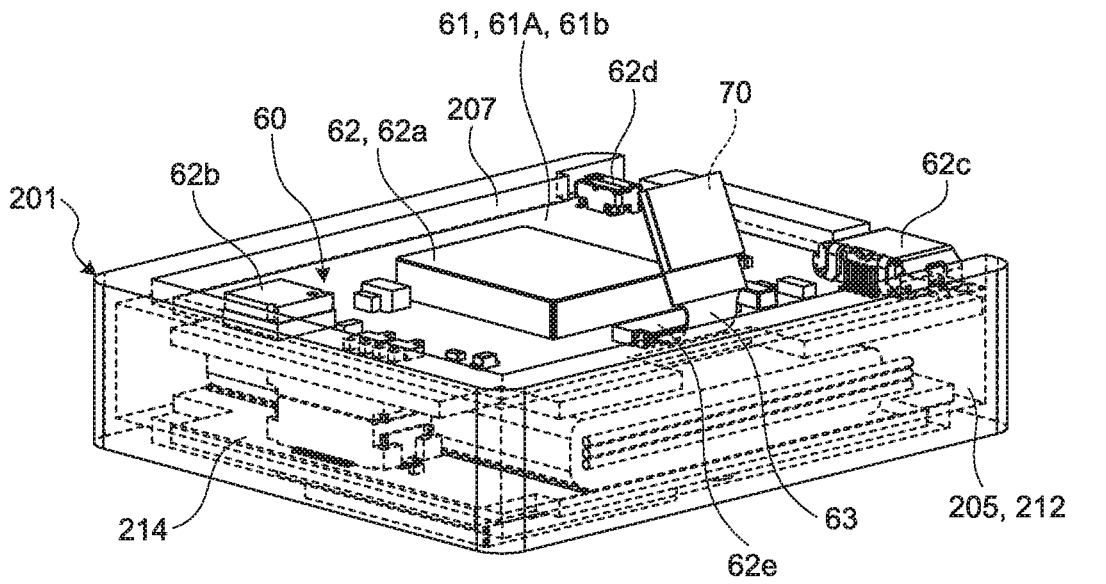


FIG. 13

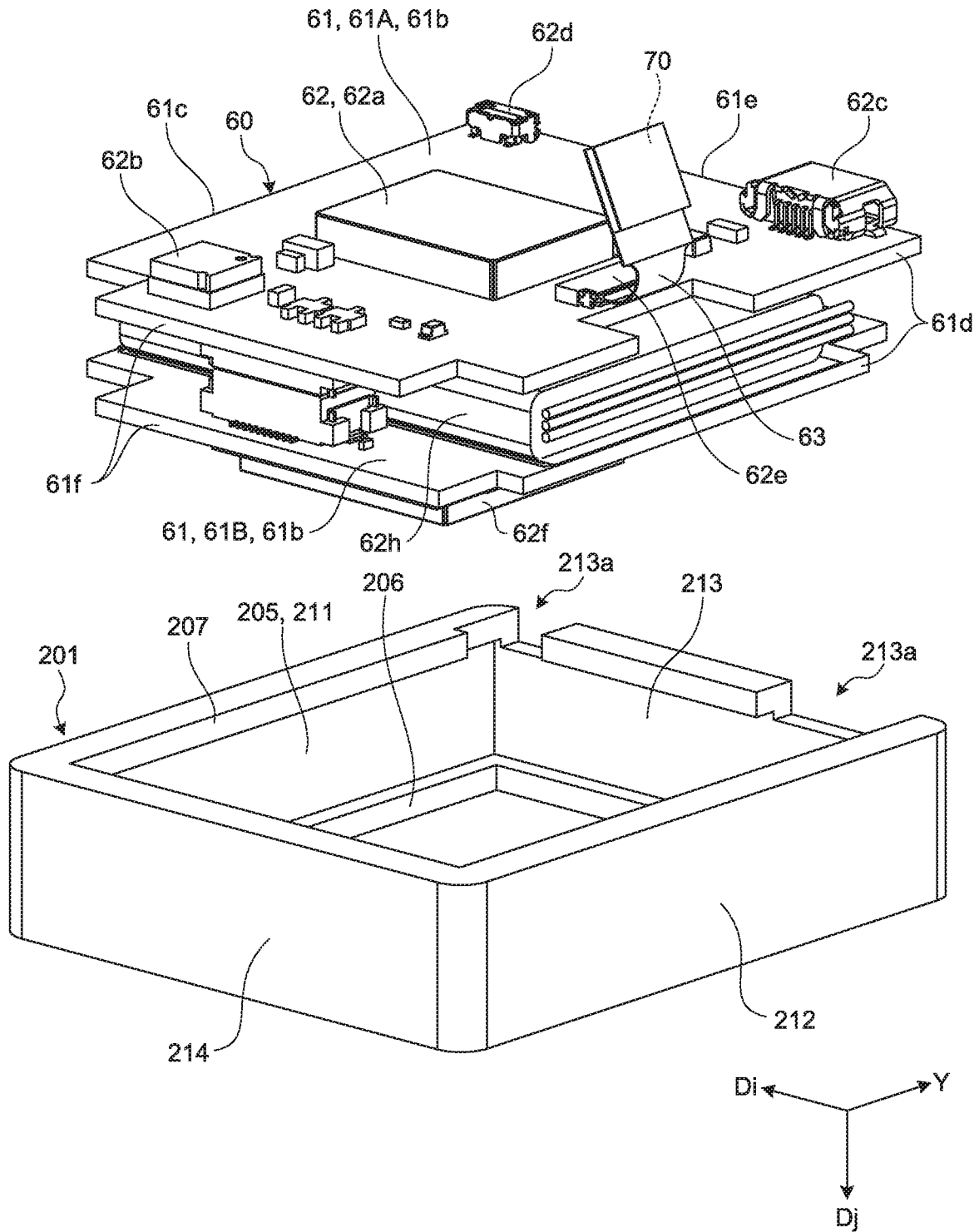


FIG. 14

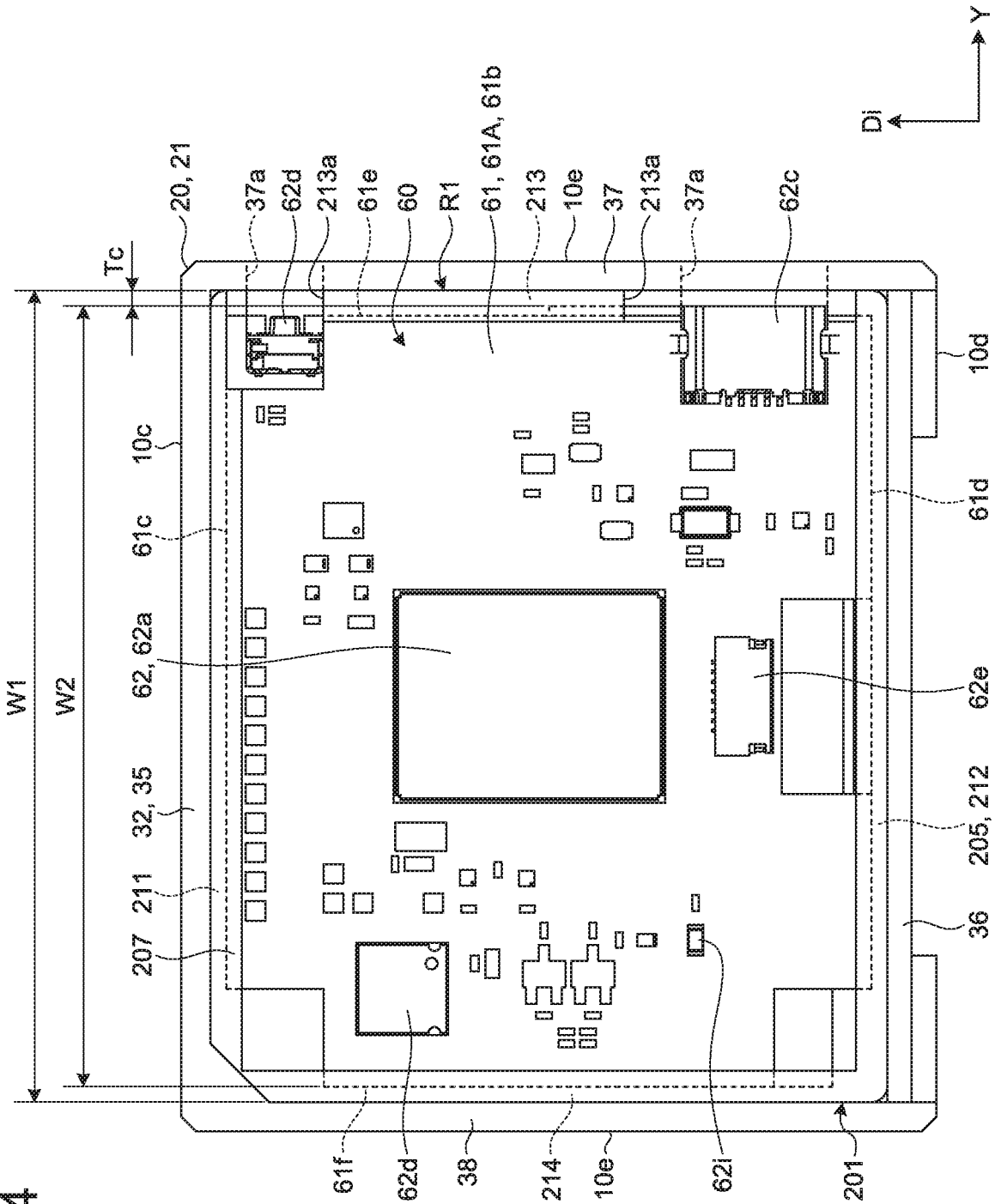


FIG.15

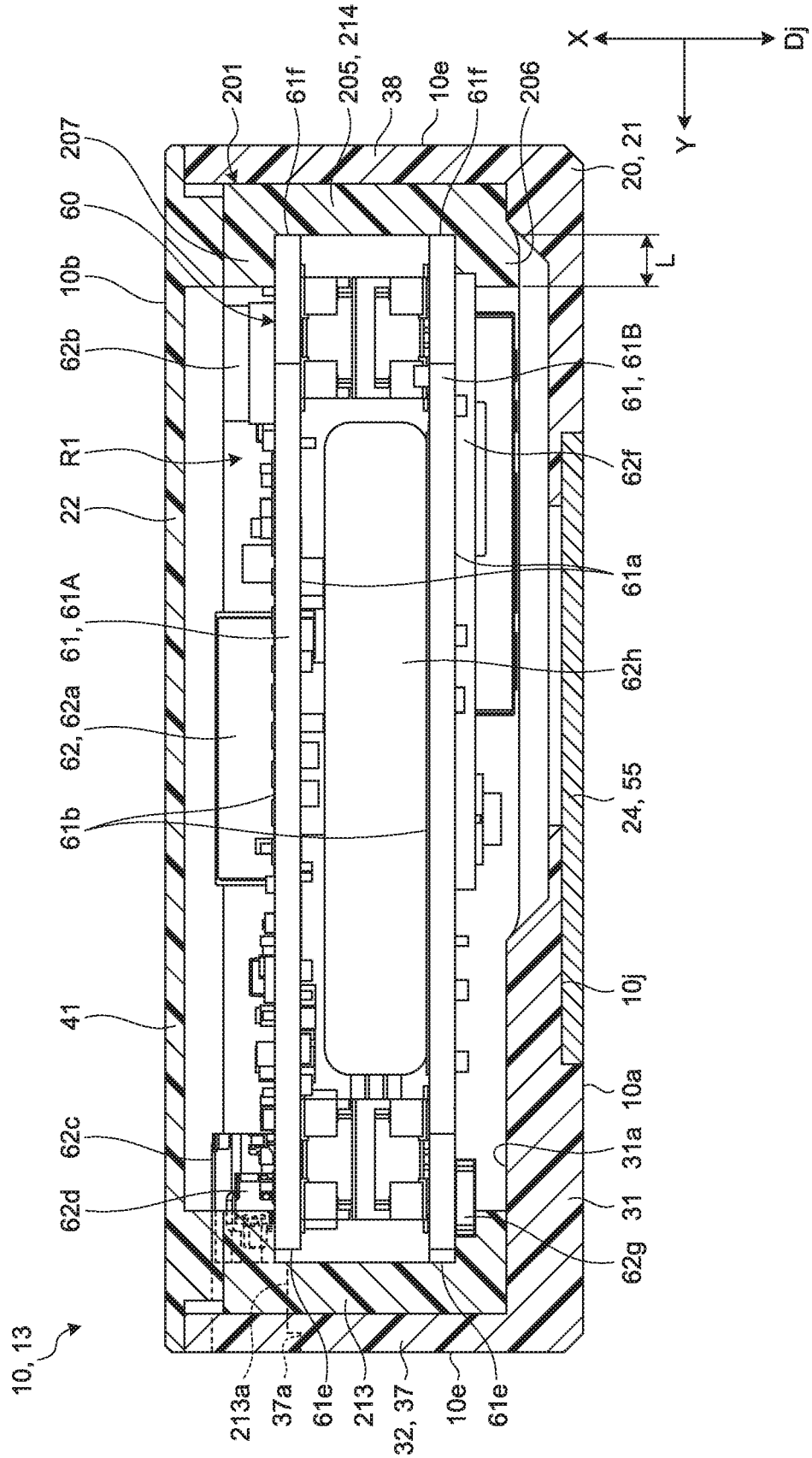
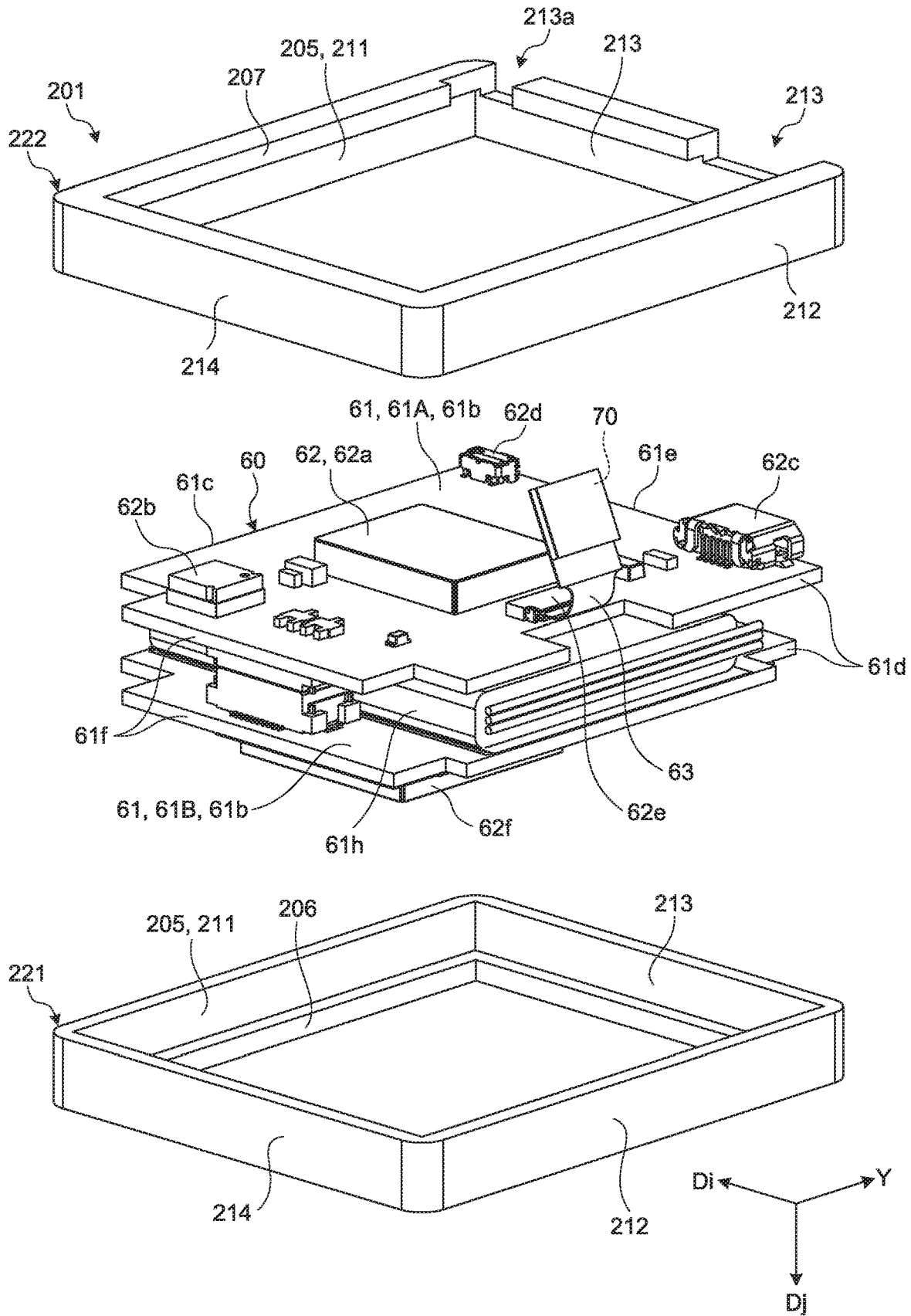


FIG. 16



VIBRATION DETECTING DEVICE**CROSS-REFERENCE TO RELATED APPLICATIONS**

[0001] This application is based upon and claims the benefit of priority from Japanese Patent Application No. 2019-122088, filed on Jun. 28, 2019; the entire contents of which are incorporated herein by reference.

FIELD

[0002] Embodiments described herein relate generally to a vibration detecting device.

BACKGROUND

[0003] Conventionally, vibration detecting devices are known, which detect vibration with a vibration sensor attached to an intended object.

[0004] It is beneficial to provide a vibration detecting device of a novel structure with less inconvenience.

BRIEF DESCRIPTION OF THE DRAWINGS

[0005] FIG. 1 is an exemplary front view illustrating a vibration detecting device according to a first embodiment;

[0006] FIG. 2 is an exemplary perspective view illustrating the vibration detecting device of the first embodiment;

[0007] FIG. 3 is an exemplary perspective view illustrating the vibration detecting device of the first embodiment, from an angle different from that of FIG. 2;

[0008] FIG. 4 is an exemplary sectional view illustrating the vibration detecting device of the first embodiment, which is taken along a line F4-F4 of FIG. 1;

[0009] FIG. 5 is an exemplary sectional view illustrating the vibration detecting device of the first embodiment, which is taken along a line F5-F5 of FIG. 1;

[0010] FIG. 6 is an exemplary perspective view illustrating a board assembly and a sheet in the first embodiment;

[0011] FIG. 7 is an exemplary front view illustrating the board assembly wrapped with the sheet in the first embodiment;

[0012] FIG. 8 is an exemplary sectional view illustrating the board assembly wrapped with the sheet together with a front case 21 in the first embodiment;

[0013] FIG. 9 is an exemplary sectional view illustrating the board assembly and the sheet accommodated in the front case in first embodiment;

[0014] FIG. 10 is an exemplary plan view illustrating a board assembly and a sheet according to a second embodiment;

[0015] FIG. 11 is an exemplary sectional view illustrating the board assembly and the sheet accommodated in a front case, according to a modification of the second embodiment;

[0016] FIG. 12 is an exemplary perspective view illustrating a front case, a board assembly, and a buffer member, according to a third embodiment, in an exploded manner;

[0017] FIG. 13 is an exemplary perspective view illustrating the board assembly and the buffer member in the third embodiment, in an exploded manner;

[0018] FIG. 14 is an exemplary back view illustrating the board assembly and the buffer member accommodated in the front case in the third embodiment;

[0019] FIG. 15 is a sectional view illustrating a vibration detecting device according to the third embodiment; and

[0020] FIG. 16 is an exemplary perspective view illustrating a board assembly and a buffer member according to a fourth embodiment, in an exploded manner.

DETAILED DESCRIPTION

[0021] In general, according to one embodiment, a vibration detecting device includes a housing, a vibration sensor, a circuit board, a flexible wiring member, and an elastic member. The vibration sensor is accommodated in the housing. The circuit board is accommodated in the housing, and is equipped with a first electric component. The first electric component is configured to process a detection signal of the vibration sensor. The wiring member electrically connects the vibration sensor and the circuit board to each other. The elastic member contains a polymer material, and is accommodated in the housing in contact with the housing and the circuit board, and is detachable from the housing. The circuit board is held by the housing through the elastic member.

First Embodiment

[0022] First, an explanation will be given of a first embodiment with reference to FIGS. 1 to 9. In the present specification, a plurality of expressions may be used in terms of a constituent element according to an embodiment and description on the element. The constituent elements and description thereof are merely exemplary, and are not limited by the expressions given in the present specification. A constituent element may be identified with a name different from that in the present specification. Further, a constituent element may be described by using an expression different from that in the present specification.

[0023] FIG. 1 is an exemplary front view illustrating a vibration detecting device 10 according to the first embodiment. FIG. 2 is an exemplary perspective view illustrating the vibration detecting device 10 of the first embodiment. FIG. 3 is an exemplary perspective view illustrating the vibration detecting device 10 of the first embodiment, from an angle different from that of FIG. 2.

[0024] As illustrated in FIG. 1, the vibration detecting device 10 is attached to a surface 100a of an intended object 100, to detect vibration of the object 100, for example. As illustrated in FIGS. 1 to 3, the vibration detecting device 10 includes an attachment 11, a base 12, and an overhang 13.

[0025] As illustrated in the respective figures, in the present specification, an X-axis, a Y-axis, and a Z-axis are defined for the sake of convenience. The X-axis, the Y-axis, and the Z-axis are orthogonal to one another. The X-axis is along the depth of the vibration detecting device 10. The Y-axis is along the width of the vibration detecting device 10. The Z-axis is along the height of the vibration detecting device 10.

[0026] Further, in the present specification, an X direction, a Y direction, and a Z direction are defined. The X direction is along the X-axis, and includes a +X direction indicated by the arrow of the X-axis, and a -X direction opposite to the arrow of the X-axis. The Y direction is along the Y-axis, and includes a +Y direction indicated by the arrow of the Y-axis, and a -Y direction opposite to the arrow of the Y-axis. The Z direction is along the Z-axis, and includes a +Z direction indicated by the arrow of the Z-axis, and a -Z direction opposite to the arrow of the Z-axis.

[0027] Further, in the present specification, a Di direction and a Dj direction are defined. The Di direction, the Dj direction, and the Y direction are orthogonal to one another. The Di direction is a direction in which the overhang 13 extends, and includes a +Di direction indicated by an arrow Di, and a -Di direction as the direction opposite to the arrow Di. The Dj direction is the thickness direction of the overhang 13, and is orthogonal to the Di direction. The Dj direction includes a +Dj direction indicated by an arrow Dj, and a -Dj direction opposite to the arrow Dj.

[0028] In this embodiment, the surface 100a of the object 100 is a substantially flat surface that is orthogonal to the Z-axis and faces in the +Z direction. However, the surface 100a is not limited to this example. For example, the vibration detecting device 10 may be attached to a curved surface 100a.

[0029] In the examples of the respective figures, the +Z direction is vertically upward, the -Z direction is vertically downward, and the X direction and the Y direction are horizontal directions. However, the X direction, the Y direction, and the Z direction are not limited to this example. For example, the vibration detecting device 10 may be attached to a surface 100a that faces vertically downward, in the horizontal direction, or in another direction. In other words, the positions and orientations of the vibration detecting device 10 and the surface 100a of the object 100 to which this vibration detecting device 10 is attached are not limited to specific ones, but may be selectively set from various positions and orientations.

[0030] FIG. 4 is an exemplary sectional view illustrating the vibration detecting device 10 of the first embodiment, which is taken along a line F4-F4 of FIG. 1. As illustrated in FIG. 4, the attachment 11 includes a stationary part 11a and a male screw 11b.

[0031] As illustrated in FIG. 1, the stationary part 11a has a substantially disk shape and is fixed to the surface 100a of the object 100. The stationary part 11a has a substantially flat attaching surface 11c that is orthogonal to the Z direction and faces in the -Z direction. The attaching surface 11c is fixed to the surface 100a by, for example, adhesion. The attachment 11 and the vibration detecting device 10 are thereby fixed to the object 100. The attachment 11 may also be referred to as bracket. As illustrated in FIG. 4, the male screw 11b protrudes from the stationary part 11a in the +Z direction.

[0032] The base 12 is detachably connected to the attachment 11. The base 12 protrudes in the +X direction from the -Di directional end of the overhang part 13. In other words, the overhang part 13 protrudes in the +Di direction from the -X directional end of the base 12.

[0033] The base 12 and the overhang 13 together form a substantially L-shape or substantially V-shape. The Di direction is slanted with respect to the Z direction. For example, the angle between the Z direction and the Di direction is an acute angle. Thus, the overhang part 13 extends obliquely from the base 12 with respect to the Z direction in which the attaching surface 11c faces.

[0034] The overhang part 13 has a flat rectangular parallelepiped shape. For example, the length (width) of the overhang part 13 in the Y direction is substantially constant. The length (thickness) of the overhang part 13 in the Dj direction is substantially constant. The shape of the overhang 13 is not limited to this example.

[0035] As illustrated in FIGS. 1 to 4, the vibration detecting device 10 includes outer surfaces, i.e., a front surface 10a, a rear surface 10b, a top surface 10c, a bottom surface 10d, lateral surfaces 10e, a front lower surface 10f, a rear upper surface 10g, a rear end surface 10h, and rear lateral surfaces 10i. Throughout the present specification, expressions representing directions, such as front, rear, upper, lower, top, bottom, and lateral, are used with reference to the accompanying drawings for the sake of convenience, and they are not intended to limit the position and direction of each element. For example, the top surface 10c may be located below the bottom surface 10d in the vertical direction.

[0036] The front surface 10a is located at the end of the overhang 13 in the +Dj direction and is substantially orthogonal to the Dj direction. The rear surface 10b is located at the end of the overhang 13 in the -Dj direction and is substantially orthogonal to the Dj direction.

[0037] The top surface 10c is located at the end of the overhang 13 in the +Di direction and is substantially orthogonal to the Di direction. The bottom surface 10d is located at the end of the base 12 in the -Z direction and is substantially orthogonal to the Z direction. The bottom surface 10d is substantially parallel to the surface 100a of the object 100 and the attaching surface 11c of the attachment 11.

[0038] The lateral surfaces 10e are located at the opposite ends of the overhang 13 in the Y direction and are substantially orthogonal to the Y direction. The front lower surface 10f is located at the end of the overhang 13 in the -Di direction and is substantially orthogonal to the Di direction.

[0039] The rear upper surface 10g is located at the end of the base 12 in the +Di direction and is substantially orthogonal to the Di direction. The rear end surface 10h is located at the end of the base 12 in the -Dj direction and is substantially orthogonal to the Dj direction. The rear lateral surfaces 10i are located at the opposite ends of the base 12 in the Y direction and are substantially orthogonal to the Y direction.

[0040] The vibration detecting device 10 includes a housing 20. The housing 20 includes a front case 21, a back cover 22, a bottom frame 23, and a shield 24. The front case 21 is an example of a box member. The back cover 22 is an example of a lid member.

[0041] Each of the front case 21 and the back cover 22 is made of a material having electromagnetic-wave transmissivity, such as a synthetic resin material or elastomer. Each of the bottom frame 23 and the shield 24 is made of a metal material having an electromagnetic-wave shielding property, such as an aluminum alloy (aluminum-based material), stainless steel (iron-based material), or magnesium alloy (magnesium-based material). The materials of the front case 21, the back cover 22, the bottom frame 23, and the shield 24 are not limited to this example.

[0042] The front case 21 includes a front wall 31 and a peripheral wall 32. The front wall 31 is substantially orthogonal to the Dj direction, and forms part of the front surface 10a of the vibration detecting device 10. The front wall 31 includes a substantially flat inner surface 31a that faces in the -Dj direction. The peripheral wall 32 has a substantially rectangular frame shape, and protrudes in the -Dj direction from the inner surface 31a. The peripheral wall 32 includes an upper wall 35, a lower wall 36, a left wall 37, and a right wall 38.

[0043] The upper wall 35 protrudes from the end of the inner surface 31a in the +Di direction. The upper wall 35 is substantially orthogonal to the Di direction, and forms part of the top surface 10c of the vibration detecting device 10. The lower wall 36 protrudes from the end of the inner surface 31a in the -Di direction. The lower wall 36 is substantially orthogonal to the Di direction, and forms part of the front lower surface 10f. Thus, the lower wall 36 is separated from the upper wall 35 in the -Di direction along the inner surface 31a.

[0044] The left wall 37 protrudes from the end of the inner surface 31a in the +Y direction. The left wall 37 is substantially orthogonal to the Y direction, and forms one of the lateral surfaces 10e of the vibration detecting device 10. The right wall 38 protrudes from the end of the inner surface 31a in the -Y direction. The right wall 38 is substantially orthogonal to the Y direction, and forms the other of the lateral surfaces 10e of the vibration detecting device 10. Thus, the right wall 38 is separated from the left wall 37 in the -Y direction along the inner surface 31a. The left wall 37 and the right wall 38 connect the opposite ends of the upper wall 35 to the opposite ends of the lower wall 36 in the Y direction.

[0045] The lengths (protruding amounts) of the upper wall 35, the left wall 37, and the right wall 38 in the Dj direction are substantially equal to each other. In the Dj direction the length of the lower wall 36 is shorter than the respective lengths of the upper wall 35, the left wall 37, and the right wall 38. The upper wall 35, the lower wall 36, the left wall 37, and the right wall 38 may have the same length or different lengths from one another.

[0046] As described above, the front case 21 has a box shape with an open end in the -Dj direction. Consequently, the front case 21 is provided with a first compartment R1 inside. The first compartment R1 is defined by the front wall 31 and the peripheral wall 32.

[0047] As illustrated in FIG. 2, the left wall 37 of the front case 21 is provided with a plurality of first holes 37a. Each of the first holes 37a is an example of a first opening. Each first hole 37a penetrates the left wall 37, and allows the first compartment R1 to communicate with the outside of the housing 20. Each first hole 37a is not limited to a hole, but may be a cutout, for example.

[0048] As illustrated in FIG. 3, the back cover 22 includes a rear wall 41, a rear upper wall 42, a rear end wall 43, and rear lateral walls 44. The rear wall 41 is substantially orthogonal to the Dj direction, and forms the rear surface 10b of the vibration detecting device 10. The rear upper wall 42 protrudes from the end of the rear wall 41 in the -Dj direction. The rear upper wall 42 is substantially orthogonal to the Di direction, and forms the rear upper surface 10g. The rear end wall 43 protrudes from the end of the rear upper wall 42 in the -Dj direction. The rear end wall 43 is substantially orthogonal to the Dj direction, and forms the rear end surface 10h. The rear lateral walls 44 are connected to the opposite ends of the rear upper wall 42 and the rear end wall 43 in the Y direction. The rear lateral walls 44 are substantially orthogonal to the Y direction, and form the rear lateral surfaces 10i.

[0049] The rear wall 41 is provided with a hole 41a. The hole 41a penetrates the rear wall 41, and allows the first compartment R1 to communicate with the outside of the housing 20. The hole 41a is not limited to a hole, but may be a cutout, for example.

[0050] The back cover 22 is attached to the -Dj directional end of the peripheral wall 32 by, for example, an adhesive. Consequently, the back cover 22 closes the first compartment R1 inside the front case 21.

[0051] As illustrated in FIG. 4, the rear upper wall 42, the rear end wall 43, and the rear lateral walls 44 of the back cover 22 have a box shape with open ends in the +Dj direction and the -Z direction. Consequently, the back cover 22 is provided with a second compartment R2 inside. The second compartment R2 is a space defined by the rear upper wall 42, the rear end wall 43, and the rear lateral walls 44. The second compartment R2 communicates with the end of the first compartment R1 in the -Di direction.

[0052] The bottom frame 23 includes a front lower wall 51 and a bottom wall 52. The front lower wall 51 is substantially orthogonal to the Di direction, and forms part of the front lower surface 10f of the vibration detecting device 10. The bottom wall 52 protrudes in the +X direction from the -Dj directional end of the front lower wall 51. The bottom wall 52 is substantially orthogonal to the Z direction, and forms the bottom surface 10d. The bottom wall 52 is provided with a female screw 52a to which the male screw 11b of the attachment 11 is detachably fastened.

[0053] The front lower wall 51 of the bottom frame 23 is attached to the lower wall 36 of the front case 21. Consequently, the bottom frame 23 is attached to the front case 21, and the bottom wall 52 of the bottom frame 23 closes the second compartment R2 of the back cover 22.

[0054] The shield 24 is fitted to a groove 10j extending in the front surface 10a, the top surface 10c, and the front lower surface 10f. The groove 10j and the shield 24 are provided at substantially the center of the front case 21 in the Y direction. The shield 24 includes a front cover wall 55, an upper cover wall 56, and a lower cover wall 57.

[0055] The front cover wall 55 is substantially orthogonal to the Dj direction, and forms part of the front surface 10a of the vibration detecting device 10. The upper cover wall 56 protrudes in the -Dj direction from the +Di directional end of the front cover wall 55. The upper cover wall 56 is substantially orthogonal to the Di direction, and forms part of the top surface 10c. The lower cover wall 57 protrudes in the -Dj direction from the -Di directional end of the front cover wall 55. The lower cover wall 57 is substantially orthogonal to the Di direction, and forms part of the front lower surface 10f.

[0056] The base 12 of the vibration detecting device 10 includes the rear upper wall 42, the rear end wall 43, and the rear lateral walls 44 of the back cover 22, and the bottom wall 52 of the bottom frame 23. The overhang 13 includes the front wall 31 and the peripheral wall 32 of the front case 21, the rear wall 41 of the back cover 22, the front lower wall 51 of the bottom frame 23, and the front cover wall 55, the upper cover wall 56, and the lower cover wall 57 of the shield 24. The first compartment R1 is provided at the overhang 13 inside the housing 20, and the second compartment R2 is provided at the base 12 inside the housing 20.

[0057] The vibration detecting device 10 includes a board assembly 60. The board assembly 60 includes a plurality of circuit boards 61, a plurality of electric components 62, and a flexible printed wiring board (flexible printed circuit board; FPC) 63. The FPC 63 is an example of a wiring member. The number of circuit boards 61 in the board assembly 60 may be one or three or more. Further, the wiring

member is not limited to the FPC 63, but may be another wiring member with flexibility, such as a flexible flat cable or a plurality of cables.

[0058] Each of the circuit boards 61 is a printed circuit board (PCB), for example. Each circuit board 61 may be another circuit board, such as a FPC. Further, the circuit boards 61 may include a plurality of types of circuit board 61.

[0059] The circuit boards 61 are electrically connected to each other through, for example, a connector, and are accommodated in the first compartment R1 inside the housing 20. Thus, the inner surface 31a of the front wall 31 of the front case 21 faces the circuit boards 61. The peripheral wall 32 surrounds the circuit boards 61.

[0060] The circuit boards 61 have a substantially rectangular plate shape substantially orthogonal to the Dj direction. The circuit boards 61 may have another shape, such as a circular shape. The circuit boards 61 are arranged with a gap along the thickness (in Dj direction).

[0061] In this embodiment, the circuit boards 61 include a circuit board 61A and a circuit board 61B. The circuit board 61A is closer to the rear wall 41 than the circuit board 61B is. The circuit boards 61A and 61B have substantially the same sizes. The circuit boards 61 may include a plurality of circuit boards 61 having sizes different from each other.

[0062] FIG. 5 is an exemplary sectional view illustrating the vibration detecting device 10 of the first embodiment, which is taken along a line F5-F5 of FIG. 1. As illustrated in FIGS. 4 and 5, each of the circuit boards 61 includes a front surface 61a, a rear surface 61b, an upper end 61c, a lower end 61d, a left end 61e, and a right end 61f. The rear surface 61b of the circuit board 61A is an example of a first surface. The front surface 61a of the circuit board 61B is an example of a second surface. The upper end 61c of each of the circuit boards 61A and 61B is an example of a first end. The lower end 61d of each of the circuit boards 61A and 61B is an example of a second end. The left end 61e of each of the circuit boards 61A and 61B is an example of a third end. The right end 61f of each of the circuit boards 61A and 61B is an example of a fourth end.

[0063] The front surface 61a is substantially flat, and faces in the +Dj direction. The rear surface 61b is substantially flat, and faces in the -Dj direction. The rear surface 61b is opposite to the front surface 61a. The front surface 61a of the circuit board 61A faces the rear surface 61b of the circuit board 61B with a gap therebetween. Further, the front surface 61a of the circuit board 61B is opposite the rear surface 61b of the circuit board 61A in the board assembly 60.

[0064] The upper end 61c is the +Di directional end of each circuit board 61. The +Di direction is along the front surface 61a, and is an example of a first direction. The lower end 61d is the -Di directional end of each circuit board 61. The -Di direction is opposite to the +Di direction, and is an example of a second direction. The lower end 61d is opposite to the upper end 61c. The upper end 61c and the lower end 61d extend in the Y direction.

[0065] The left end 61e is the +Y directional end of each circuit board 61. The +Y direction is along the front surface 61a and orthogonal to the +Di direction, and is an example of a third direction. The left end 61e is located between the end of the upper end 61c and the end of the lower end 61d in the +Y direction.

[0066] The right end 61f is the end of each circuit board 61 in the -Y direction. The -Y direction is opposite to the +Y direction, and is an example of a fourth direction. The right end 61f is located between the end of the upper end 61c in the -Y direction and the end of the lower end 61d in the -Y direction. The right end 61f is opposite to the left end 61e. The left end 61e and the right end 61f extend in the Di direction.

[0067] The electric components 62 include a micro controller unit (MCU) 62a, a first wireless unit 62b, an external connector 62c, an external operation switch 62d, a connector 62e, a second wireless unit 62f, an antenna 62g, and a battery 62h. The MCU 62a is an example of a first electric component. Each of the external connector 62c and the external operation switch 62d is an example of a second electric component.

[0068] The MCU 62a, the first wireless unit 62b, the external connector 62c, the external operation switch 62d, and the connector 62e are mounted on the rear surface 61b of the circuit board 61A. The MCU 62a is placed in substantially the center of the rear surface 61b in the Y direction. The first wireless unit 62b is placed at the end of the rear surface 61b in the -Y direction. The external connector 62c and the external operation switch 62d are arranged at the end of the rear surface 61b in the +Y direction. The connector 62e is placed at the end of the rear surface 61b in the -Di direction.

[0069] The second wireless unit 62f and the antenna 62g are mounted on the front surface 61a of the circuit board 61B. The antenna 62g is placed at the end of the front surface 61a in the +Y direction. The battery 62h is mounted on the front surface 61a of the circuit board 61A or the rear surface 61b of the circuit board 61B.

[0070] The first wireless unit 62b incorporates an antenna, and communicates data in compliance with, for example, the Bluetooth (registered trademark) low energy (BLE) standard. The second wireless unit 62f executes data communication via the antenna 62g in compliance with, for example, long range wide area network (LoRaWAN) (registered trademark) standard.

[0071] The first wireless unit 62b and the antenna 62g are covered with the front case 21 and the back cover 22 having electromagnetic-wave transmittivity. Consequently, the wireless communication between the first wireless unit 62b and the antenna 62g cannot be jammed.

[0072] The MCU 62a is covered with the shield 24 through the front case 21. Consequently, the MCU 62a can be prevented from being affected by noise. Further, the shield 24 is located between the first wireless unit 62b and the antenna 62g in the Y direction to reduce interference between a communication signal of the first wireless unit 62b and a communication signal of the antenna 62g.

[0073] As illustrated in FIG. 4, the FPC 63 is connected to the circuit board 61A through the connector 62e. The FPC 63 is accommodated in the first compartment R1 and the second compartment R2 inside the housing 20. In other words, the FPC 63 extends across the first compartment R1 and the second compartment R2.

[0074] The FPC 63 has flexibility and extends between a first end 63a and a second end 63b in a flexural manner. The first end 63a is inside the first compartment R1, and is inserted into the connector 62e. The second end 63b is inside the second compartment R2.

[0075] The vibration detecting device 10 further includes a vibration sensor 70. The vibration sensor 70 is mounted at the second end 63b of the FPC 63. The vibration sensor 70 is accommodated in the second compartment R2 inside the housing 20. Further, the FPC 63 electrically connects the vibration sensor 70 to the circuit board 61A.

[0076] For example, the vibration sensor 70 is a shock sensor. The vibration sensor 70 may be another vibration sensor, such as a piezoelectric vibration sensor, micro electro mechanical systems (MEMS) vibration sensor, or tri-axial acceleration sensor.

[0077] The vibration sensor 70 outputs a detection signal to the MCU 62a through the FPC 63. The MCU 62a processes the detection signal of the vibration sensor 70, and controls the first wireless unit 62b and the second wireless unit 62f to wirelessly transmit a signal in accordance with this detection signal. The MCU 62a is not limited to this example.

[0078] At least one of the vibration sensor 70 and the second end 63b is directly or indirectly attached to a mounting surface 23a of the bottom frame 23 with, for example, an adhesive or a sealing material. The mounting surface 23a is located in the second compartment R2. Specifically, in the second compartment R2, the periphery of the vibration sensor 70 is covered by the adhesive or sealing material and thereby fixed so as not to move. Further, the adhesive or sealing material around the vibration sensor 70 work to reduce transmission of vibration to the vibration sensor 70 from parts or elements other than the mounting surface 23a.

[0079] The FPC 63 includes a bend 63c between the first end 63a and the second end 63b. The FPC 63 is separated from the housing 20 at least in the vicinity of the bend 63c. Thereby, the FPC 63 is changeable in shape (position, radius of curvature, etc.) at the bend 63c, and can restrict transmission of vibration from the housing 20 to the vibration sensor 70 through the FPC 63.

[0080] As illustrated in FIG. 5, the vibration detecting device 10 further includes a flexible sheet 80. The sheet 80 is an example of an elastic member. FIG. 4 omits depicting the sheet 80. The sheet 80 can be of a plate form, layer form, or film form, and be a member spreadable to be orthogonal to or intersect with a desired direction. The sheet 80 may also be referred to as buffer material.

[0081] For example, the sheet 80 is made of a gel, such as α GEL (registered trademark). In other words, the sheet 80 is made of a polymer material. The sheet 80 may be made of another gel, a synthetic resin such as silicone or elastomer, a sponge, or another polymer material having flexibility. The sheet 80 is substantially transparent, for example, but may have a color.

[0082] The sheet 80 is flexible and stretchable. Specifically, the sheet 80 is lower in longitudinal elastic modulus and in shear elastic modulus (rigidity modulus) than the housing 20 and the circuit boards 61, and is easily stretchable and bendable. The sheet 80 is not limited to this example.

[0083] The sheet 80 is bent to wrap around the circuit boards 61, and is accommodated together with the circuit boards 61 in the first compartment R1 inside the housing 20. The sheet 80 is in contact with the housing 20 and the circuit boards 61 and separable or detachable therefrom. The sheet 80 is interposed between the housing 20, and each of the rear surface 61b of the circuit board 61A, the front surface 61a

of the circuit board 61B, and the upper end 61c, the lower end 61d, the left end 61e, and the right end 61f of each of the circuit boards 61A and 61B. Consequently, the circuit boards 61 are held by the housing 20 through the sheet 80 at positions separated from the housing 20.

[0084] FIG. 6 is an exemplary perspective view illustrating the board assembly 60 and the sheet 80 in the first embodiment. As illustrated in FIG. 6, the sheet 80 of this embodiment, when spread, has a substantially cross shape, and includes a base 81, an upper extension 82, a lower extension 83, a left extension 84, and a right extension 85. The sheet 80 may have another shape.

[0085] The base 81 has a substantially rectangular shape, and covers the front surface 61a of the circuit board 61B. The base 81 has substantially the same size as the circuit board 61B. The base 81 may be smaller or larger than the circuit board 61B.

[0086] The upper extension 82 extends from the end of the base 81 in the +Di direction. Being bent, the upper extension 82 covers the upper end 61c of each of the circuit boards 61A and 61B and part of the rear surface 61b of the circuit board 61A. The lower extension 83 extends from the end of the base 81 in the -Di direction. Being bent, the lower extension 83 covers the lower end 61d of each of the circuit boards 61A and 61B and part of the rear surface 61b of the circuit board 61A.

[0087] The left extension 84 extends from the end of the base 81 in the +Y direction. Being bent, the left extension 84 covers the left end 61e of each of the circuit boards 61A and 61B and part of the rear surface 61b of the circuit board 61A. The right extension 85 extends from the end of the base 81 in the -Y direction. Being bent, the right extension 85 covers the right end 61f of each of the circuit boards 61A and 61B and part of the rear surface 61b of the circuit board 61A.

[0088] The lower extension 83 is provided with an insertion hole 83a. The insertion hole 83a penetrates the lower extension 83. Further, the left extension 84 is provided with a plurality of second holes 84a. Each of the second holes 84a is an example of a second opening. Each second hole 84a penetrates the left extension 84. The insertion hole 83a and the second holes 84a is not limited to holes, but may be cutouts, for example.

[0089] The corner 86A between the upper extension 82 and the left extension 84, the corner 86B between the upper extension 82 and the right extension 85, the corner 86C between the lower extension 83 and the left extension 84, and the corner 86D between the lower extension 83 and the right extension 85 are finished by round chamfering and has a substantially arc shape. Thus, the corners 86A, 86B, 86C, and 86D can be prevented from cracking.

[0090] FIG. 7 is an exemplary front view illustrating the board assembly 60 wrapped with the sheet 80 in the first embodiment. The FPC 63 extends between the circuit board 61A and the vibration sensor 70 through the insertion hole 83a. The external connector 62c and the external operation switch 62d are exposed outside the housing 20 through the second holes 84a of the sheet 80 and the first holes 37a of the housing 20. The first holes 37a may be closed by a cover or another component. Further, the external connector 62c and the external operation switch 62d are separated from the housing 20.

[0091] Owing to the substantially transparent sheet 80, for example, the circuit boards 61 are visible from outside the housing 20 through the hole 41a of FIG. 3 and the sheet 80.

For example, as illustrated in FIG. 6, the light of an LED 62i mounted on the circuit board 61A is visible from outside the housing 20 through the hole 41a and the sheet 80.

[0092] As illustrated in FIGS. 5 and 6, the sheet 80 further includes a first surface 80a, a second surface 80b, and an edge 80c. The first surface 80a is an example of a surface. The first surface 80a faces the circuit boards 61. The second surface 80b is opposite to the first surface 80a, and faces the housing 20. The edge 80c is the edge of the sheet 80 in the directions along the first surface 80a. Each of the base 81, the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85 includes part of the first surface 80a, the second surface 80b, and the edge 80c.

[0093] The sheet 80 having the above-described shape is produced, for example, by cutting part of a substantially rectangular material. The sheet 80 is not limited to this example, but may be produced in the above shape without cutting.

[0094] Next, an exemplary explanation will be given of part of an assembling method of the vibration detecting device 10. The assembling method of the vibration detecting device 10 is not limited to the following method, but the vibration detecting device 10 may be assembled by another method. First, as illustrated in FIG. 6, the board assembly 60 excluding the FPC 63 is assembled. Alternatively, the board assembly 60 including the FPC 63 may be assembled.

[0095] Then, the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85 of the sheet 80 are bent to wrap around the circuit boards 61. As illustrated in FIG. 7, the sheet 80 wraps around the circuit boards 61 with the MCU 62a exposed. The MCU 62a may be covered with the sheet 80.

[0096] FIG. 8 is an exemplary sectional view illustrating the board assembly 60 wrapped with the sheet 80 together with the front case 21 in the first embodiment. As illustrated in FIG. 8, the sheet 80 includes a plurality of bends 88 to be in contact with the circuit boards 61 and a plurality of electric components 62. Specifically, being bent at the bends 88, the sheet 80 can be in contact with the circuit boards 61 and a plurality of electric components 62 different in thickness.

[0097] The sheet 80 includes mutually overlapping portions. For example, part of the lower extension 83 and part of the left extension 84 are overlapped with each other. Part of the lower extension 83 and part of the right extension 85 are overlapped with each other. Part of the upper extension 82 and part of the left extension 84 are overlapped with each other. Part of the upper extension 82 and part of the right extension 85 are overlapped with each other.

[0098] Of the sheet 80, one part and another part of the overlapping portions are in direct contact with each other without an adhesive or a double-sided adhesive tape. Because of this, one part and another part of the overlapping portions of the sheet 80 are separable or detachable from each other. One part and another part of the overlapping portions of the sheet 80 may separably stick to each other by the stickiness of the sheet 80.

[0099] Then, the circuit boards 61 and the sheet 80 are press-fitted into the first compartment R1 of the front case 21. Consequently, the sheet 80 is interposed between the housing 20 and each of the front surface 61a of the circuit board 61B and the upper end 61c, the lower end 61d, the left end 61e, and the right end 61f of each of the circuit boards 61A and 61B.

[0100] FIG. 9 is an exemplary sectional view illustrating the board assembly 60 and the sheet 80 accommodated in the front case 21 in first embodiment. The edge 80c of the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85, which is indicated by a two-dot chain line in FIG. 9, is not fixed, therefore, free. That is, by pressing the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85 with a jig, for example, the sheet 80 is restricted from separating from the board assembly 60 due to the restoring force.

[0101] Then, the FPC 63 is inserted into the connector 62e through the insertion hole 83a. The bottom frame 23 is attached to the front case 21. The FPC 63 and the vibration sensor 70 are attached to the bottom frame 23.

[0102] Then, as indicated by a two-dot chain line in FIG. 5, the back cover 22 is attached to the front case 21. The back cover 22 is fixed to the front case 21 while the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85 are pressed against the circuit boards 61. In the example of FIG. 5, the back cover 22 is moved in the +Dj direction for attachment to the front case 21. However, for example, the back cover 22 may be rotated around the Y-axis and attached to the front case 21.

[0103] The edge 80c of the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85 extends between the circuit boards 61 and the back cover 22. Thus, the back cover 22 works to press the upper extension 82, the lower extension 83, the left extension 84, and the right extension 85 to restrict the sheet 80 from moving away from the board assembly 60 by the restoring force.

[0104] As illustrated in FIG. 9, in the Y direction the distance W1 (the width of the first compartment R1) between the left wall 37 and the right wall 38 is larger than the distance (width) W2 between the left end 61e and the right end 61f of each circuit board 61.

[0105] As illustrated in FIG. 8, in the natural, uncompressed state, the distance (thickness) T between the first surface 80a and the second surface 80b of the sheet 80 is larger than a half of the difference between the width W1 and the width W2. Specifically, the relationship between the thickness T, and the width W1 and the width W2 can be expressed by the following Formula 1:

$$T > 1/2(W1 - W2).$$

[0106] Due to the dimensional difference described above, while the board assembly 60 and the sheet 80 are accommodated in the first compartment R1, the sheet 80 is compressed between the circuit boards 61 and the housing 20. Thus, the sheet 80 extends between the circuit boards 61 and the housing 20 in a compressed state. The sheet 80 may include a non-compressible part.

[0107] As illustrated in FIG. 9, when compressed, the sheet 80 decreases in thickness to a thickness T' about 80% of the thickness T in the natural state, for example. The thickness T' is not limited to this example, but the thickness T' of the sheet 80 is set to exhibit desired vibration absorbing performance.

[0108] The dimensional difference described above is not limited to the one between the width W1 between the left wall 37 and the right wall 38 and the width W2 between the left end 61e and the right end 61f of each circuit board 61. The sheet 80 is compressed between the rear surface 61b of the circuit board 61A and the back cover 22, between the

front surface **61a** of the circuit board **61B** and the front wall **31**, and between the peripheral wall **32**, and the upper end **61c**, the lower end **61d**, the left end **61e**, and the right end **61f** of each of the circuit boards **61A** and **61B**.

[0109] Due to the stretching properties, the sheet **80** can be deformed in accordance with the shape of the gap between each circuit board **61** and the housing **20**. Consequently, the sheet **80** can come into contact with each circuit board **61**, each electric component **62**, and the housing **20** in a larger contact area.

[0110] In the housing **20** the circuit boards **61** are held by the housing **20** through the bent sheet **80** wrapping around these circuit boards **61**. Specifically, the front wall **31** supports the front surface **61a** of the circuit board **61B** through the sheet **80**, the peripheral wall **32** supports the upper end **61c**, the lower end **61d**, the left end **61e**, and the right end **61f** of each of the circuit boards **61A** and **61B** through the sheet **80**, and the rear wall **41** supports the rear surface **61b** of the circuit board **61A** through the sheet **80**. Consequently, the movement of the circuit boards **61** is restricted.

[0111] The sheet **80** is in direct contact with the housing **20**, each circuit board **61**, and each electric component **62** without an adhesive or a double-sided adhesive tape. Thus, the sheet **80** is in contact with the housing **20**, each circuit board **61**, and each electric component **62**, and separable (detachable) therefrom. The sheet **80** may separably stick to the housing **20**, each circuit board **61**, and each electric component **62** by the stickiness of the sheet **80**.

[0112] As described above, the circuit boards **61** are not fixed to the housing **20** with screws, pins, a double-sided tape, adhesive, or filler, but are held by the housing **20** through the sheet **80** with spacing from the housing **20**. That is, the circuit boards **61** are movable relative to the housing **20** by elastic deformation of the sheet **80**.

[0113] The sheet **80** attenuates vibration and restrains transmission of vibration between the circuit boards **61** and the housing **20**. Thus, vibration of the housing **20** can be avoided from being transmitted to the vibration sensor **70** through the circuit boards **61** and the FPC **63**. Further, the circuit boards **61** are restrained from being vibrated due to resonance.

[0114] Then, the shield **24** is attached to the front case **21** and the bottom frame **23**, and the attachment **11** is attached to the bottom frame **23**. This completes the assembly of the vibration detecting device **10**.

[0115] The board assembly **60** may be taken out of the housing **20** after production of the vibration detecting device **10**. In this case, the back cover **22** is detached from the front case **21** to open the sheet **80**, enabling extraction of the board assembly **60** from the housing **20**. That is, in the vibration detecting device **10**, the board assembly **60** can be detached from the housing **20** without removal work of adhesive or filler.

[0116] In the vibration detecting device **10** according to the first embodiment described above, the circuit boards **61** are held by the housing **20** through the sheet **80**. That is, the sheet **80** spreads between the housing **20** and the circuit boards **61** to be able to reduce transmission of vibration between the housing **20** and the circuit boards **61**, and attenuate vibration of the circuit boards **61**. This can suppress vibration noise due to vibration of the housing **20** transmitted through the circuit boards **61** and/or resonance of the circuit boards **61** from entering the vibration sensor

70, thereby reducing occurrence of malfunctions or failures in the vibration detecting device **10**. Further, since the vibration absorbing member is in the form of a sheet, the circuit boards **61** can be more easily detached from the housing **20** than a vibration absorbing material filled in-between the circuit boards **61** and the housing **20**, for example. In addition, the circuit boards **61** can be equipped with a member with a hole, such as the external connector **62c**, and/or a movable member, such as the external operation switch **62d**. Further, the sheet **80** includes the bends, so that the sheet **80** can be easily set in close contact with the circuit boards **61** and the housing **20**.

[0117] The sheet **80** contains a gel. Specifically, the sheet **80** is lower in shear elastic modulus (rigidity modulus) and is higher in viscosity than a buffer material, such as elastomer or sponge. Consequently, the sheet **80** exhibits higher stretching property to efficiently absorb and attenuate vibration and to spread between the housing **20** and the circuit boards **61** without a gap. This can prevent vibration noise from entering the vibration sensor **70**.

[0118] The sheet **80** contains α GEL. Consequently, the sheet **80** can efficiently absorb and attenuate vibration and spread between the housing **20** and the circuit boards **61** without a gap. Thus, vibration noise is restrained from entering the vibration sensor **70**.

[0119] The sheet **80** is bent to wrap around the circuit boards **61**, spreading between the housing **20**, and each of the front surfaces **61a**, the rear surfaces **61b**, the left ends **61e**, and the right ends **61f**. This can restrain the circuit boards **61** from coming into contact with the housing **20**, and suppress vibration noise due to vibration of the housing **20** transmitted through the circuit boards **61** and/or resonance of the circuit boards **61** from entering the vibration sensor **70**.

[0120] The sheet **80** spreads between the circuit boards **61** and the housing **20** in a compressed state. Specifically, the distance between the circuit boards **61** and the housing **20** is smaller than the thickness of the sheet **80** in the natural state. Consequently, the restoring force of the sheet **80** serves to hold the circuit boards **61**, and reduce vibration of the circuit boards **61**.

[0121] The housing **20** is provided with the first holes **37a**, and the sheet **80** is provided with the second holes **84a**. The external connector **62c** is mounted on the circuit boards **61**, and is exposed outside the housing **20** through one of the first holes **37a** and one of the second holes **84a**. Consequently, the external connector **62c** is usable from outside the housing **20**. For example, the external connector **62c** is operable or viewable from outside, and/or another component such as a plug is insertable into the external connector **62c**.

[0122] The front case **21** of the housing **20** includes the inner surface **31a** that faces the circuit boards **61**, and the peripheral wall **32** that protrudes from the inner surface **31a** and surrounds the circuit boards **61**. The back cover **22** is attached to an end of the peripheral wall **32** to close the inside of the front case **21** and to press part of the sheet **80** against one of the circuit boards **61**. The back cover **22** presses the sheet **80** in this manner, eliminating the necessity to attach the sheet **80** to the housing **20**, the circuit boards **61**, or another part of the sheet **80** and reducing hindrance to the vibration absorption and attenuation by the sheet **80**.

[0123] The sheet **80** includes the first surface **80a** that faces the circuit boards **61**, and the edge **80c** in the directions

along the first surface **80a**. This edge **80c** is located between the circuit boards **61** and the back cover **22**. Specifically, the back cover **22** works to press part of the sheet **80** including the edge **80c** against one of the circuit boards **61**. Consequently, the back cover **22** can be attached to the end of the peripheral wall **32**, while pressing the vicinity of the edge **80c** of the sheet **80**, which is to move away from the circuit boards **61** by the restoring force, against one of the circuit boards **61**. This facilitates the assembly of the vibration detecting device **10**.

[0124] The sheet **80** includes mutually directly contacting, overlapping portions and is in direct contact with the housing **20** and the circuit boards **61**. Specifically, the overlapping portions of the sheet **80** are not fixed to each other with a double-sided tape or an adhesive. The contacting part of the sheet **80** with the housing **20** and the circuit boards **61** are not fixed to the housing **20** and the circuit boards **61** with a double-sided tape or an adhesive. Thus, the vibration absorption and attenuation by the sheet **80** cannot be hindered by fixation.

Second Embodiment

[0125] Next, an explanation will be given of a second embodiment with reference to FIGS. **10** to **11**. In the following description of second to fourth embodiments, the constituent elements having functions substantially the same as those of constituent elements previously described are denoted by reference symbols the same as those for the constituent elements previously described, and, further, their description will be omitted in some cases. Furthermore, a plurality of constituent elements denoted by the same reference symbols are not necessarily the same in all the functions and properties, but may be different in function and/or property as needed for the respective embodiments.

[0126] FIG. **10** is an exemplary plan view illustrating a board assembly **60** and a sheet **80** according to the second embodiment. As illustrated in FIG. **10**, the sheet **80** of the second embodiment have a substantially T-shape in an unfolded state. In this case, the lower extension **83** serves to cover the upper end **61c** and the lower end **61d** of each of the circuit boards **61A** and **61B** and the front surface **61a** of the circuit board **61A**.

[0127] FIG. **11** is an exemplary sectional view illustrating the board assembly **60** and the sheet **80** accommodated in a front case **21**, according to a modification of the second embodiment. As illustrated in FIG. **11**, the lower extension **83** may cover the lower end **61d** of each of the circuit boards **61A** and **61B** and part of the front surface **61a** of the circuit board **61A**, and another buffer material **90** may cover the upper end **61c** of each of the circuit boards **61A** and **61B**.

[0128] The buffer material **90** is made of a gel, a synthetic resin, such as silicone or elastomer, a sponge, or another material. The buffer material **90** is interposed between the upper end **61c** of each of the circuit boards **61A** and **61B** and the upper wall **35** of the housing **20**. The upper wall **35** holds the upper end **61c** of each of the circuit boards **61A** and **61B** through the buffer material **90**.

[0129] In the second embodiment, the shape of the sheet **80** is not limited to the cross shape of the first embodiment. The sheet **80** may be substantially T-shaped as illustrated in FIG. **10**, or may be substantially I-shaped, substantially L-shaped, substantially rectangular, or of another shape.

[0130] The sheet **80** has a shape different from the rectangular shape and is bent to wrap around the circuit boards

61. This serves to reduce the overlapping part of the sheet **80** and to prevent increase in the thickness of the sheet **80**.

[0131] Further, another buffer material **90** may be interposed between the circuit boards **61** and the housing **20**. In this case, the sheet **80** and the buffer material **90** attenuate vibration and restrain transmission of vibration between the housing **20** and the circuit boards **61**.

Third Embodiment

[0132] Next, an explanation will be given of a third embodiment with reference to FIGS. **12** to **15**. FIG. **12** is an exemplary perspective view illustrating a front case **21**, a board assembly **60**, and a buffer member **201**, according to the third embodiment, in an exploded manner. FIG. **13** is an exemplary perspective view illustrating the board assembly **60** and the buffer member **201** in the third embodiment, in an exploded manner. FIG. **14** is an exemplary back view illustrating the board assembly **60** and the buffer member **201** accommodated in the front case **21** in the third embodiment.

[0133] In the third embodiment, the vibration detecting device **10** includes the buffer member **201** in place of the sheet **80**. The buffer member **201** is an example of an elastic member. The vibration detecting device **10** may include both of the sheet **80** and the buffer member **201**.

[0134] The buffer member **201** is made of, for example, translucent silicone rubber. Thus, the buffer member **201** is made of a polymer material. The buffer member **201** may be made of a gel, a synthetic resin, such as elastomer, a sponge, or another polymer material.

[0135] The silicone rubber as the material of the buffer member **201** is, for example, SH0010U or SH0020U of KCC Corporation, or TSE221-3U of Momentive Performance Materials Worldwide LLC. The material of the buffer member **201** is not limited to this example. The buffer member **201** is made of, for example, silicone rubber having a hardness of 20° or less. As the buffer member **201** is made of silicon rubber having low hardness, the buffer member **201** can easily attenuate vibration and easily restrain transmission of vibration, between the housing **20** and the circuit boards **61**. The hardness of the buffer member **201** is not limited to this example.

[0136] The buffer member **201** is detachably attached to the board assembly **60** including the circuit boards **61**. In other words, the buffer member **201** and the board assembly **60** mutually hold the other so as to be separable therefrom. The buffer member **201** may be simply set in contact with the board assembly **60** without being attached to the board assembly **60**.

[0137] FIG. **15** is a sectional view illustrating the vibration detecting device **10** according to the third embodiment. As illustrated in FIG. **15**, the buffer member **201** includes a frame wall **205**, a first protrusion **206**, and a second protrusion **207**.

[0138] As illustrated in FIG. **14**, the frame wall **205** has a substantially rectangular frame shape. The frame wall **205** is not limited to this example, but may have another shape, such as a circular frame shape, in accordance with the shapes of the circuit boards **61**. The frame wall **205** includes a first wall **211**, a second wall **212**, a third wall **213**, and a fourth wall **214** in a unified manner.

[0139] The first wall **211** is located at the end of the frame wall **205** in the +Di direction, and extends in the Y direction. The second wall **212** is located at the end of the frame wall

205 in the $-D_i$ direction, and extends in the Y direction. The third wall **213** is provided between the end of the first wall **211** in the $+Y$ direction and the end of the second wall **212** in the $+Y$ direction, and extends in the D_i direction. The fourth wall **214** is provided between the end of the first wall **211** in the $-Y$ direction and the end of the second wall **212** in the $-Y$ direction, and extends in the D_i direction.

[0140] As illustrated in FIG. 15, the first to fourth walls **211** to **214** have a band shape having a wider width in the D_j direction. As illustrated in FIG. 14, the first wall **211** covers the upper end **61c** of each of the circuit boards **61A** and **61B**. The second wall **212** covers the lower end **61d** of each of the circuit boards **61A** and **61B**. The third wall **213** covers the left end **61e** of each of the circuit boards **61A** and **61B**. The fourth wall **214** covers the right end **61f** of each of the circuit boards **61A** and **61B**. The upper end **61c**, the lower end **61d**, the left end **61e**, and the right end **61f** of each of the circuit boards **61A** and **61B** may be exposed without being covered by the buffer member **201** partly.

[0141] The first wall **211** is in contact with the upper end **61c** of each of the circuit boards **61A** and **61B**. The second wall **212** is in contact with the lower end **61d** of each of the circuit boards **61A** and **61B**. The third wall **213** is in contact with the left end **61e** of each of the circuit boards **61A** and **61B**. The fourth wall **214** is in contact with the right end **61f** of each of the circuit boards **61A** and **61B**. The first to fourth walls **211** to **214** may be separated from the circuit boards **61A** and **61B** partly or slightly.

[0142] The circuit boards **61A** and **61B** of the board assembly **60** are located between the first wall **211** and the second wall **212**, and are held by the first wall **211** and the second wall **212**. In other words, the first wall **211** and the second wall **212** are in contact with the upper end **61c** and the lower end **61d** of each of the circuit boards **61A** and **61B**, and thereby restrict the movement of the board assembly **60** in the D_i direction.

[0143] The circuit boards **61A** and **61B** of the board assembly **60** are located between the third wall **213** and the fourth wall **214**, and are held by the third wall **213** and the fourth wall **214**. In other words, the third wall **213** and the fourth wall **214** are in contact with the left end **61e** and the right end **61f** of each of the circuit boards **61A** and **61B**, and thereby restrict the movement of the board assembly **60** in the Y direction.

[0144] As illustrated in FIG. 15, the first protrusion **206** protrudes inward in the frame wall **205**, from the end of the frame wall **205** in the $+D_j$ direction. Accordingly, the first protrusion **206** has a substantially rectangular frame shape. The first protrusion **206** may protrude from at least one of the first to fourth walls **211** to **214**.

[0145] The second protrusion **207** protrudes inward in the frame wall **205**, from the end of the frame wall **205** in the $-D_j$ direction. Accordingly, the second protrusion **207** has a substantially rectangular frame shape. The second protrusion **207** may protrude from at least one of the first to fourth walls **211** to **214**.

[0146] The protruding length L of the first protrusion **206** from the frame wall **205** is smaller than the length of the frame wall **205** in the D_j direction. Similarly, the protruding length of the second protrusion **207** from the frame wall **205** is smaller than the length of the frame wall **205** in the D_j direction. The D_j direction is orthogonal to the front surface **61a** of each circuit board **61**. The length of the first protrusion

206 and the length of the second protrusion **207** are substantially equal to each other, but may be different from each other.

[0147] The first protrusion **206** and the second protrusion **207** are short, and thus can be easily and elastically deformed. Accordingly, the board assembly **60** can be easily accommodated into the inside of the frame wall **205**, accompanied by deformation of the first protrusion **206** or the second protrusion **207**. Thus, the buffer member **201** can be elastically attached to the board assembly **60**.

[0148] The second protrusion **207** is short, and is separated from the connector **62e** and the FPC **63**. Consequently, the second protrusion **207** does not need a hole like the insertion hole **83a** of the sheet **80**. Further, the first protrusion **206** exposes the front surface **61a** of the circuit board **61B** and electric components **62** mounted on this front surface **61a**. The second protrusion **207** exposes the rear surface **61b** of the circuit board **61A** and electric components **62** mounted on this rear surface **61b**. The first protrusion **206** and the second protrusion **207** are not limited to this example.

[0149] The first protrusion **206** is in contact with the front surface **61a** of the circuit board **61B**. The first protrusion **206** may be further in contact with electric components **62** mounted on the front surface **61a** of the circuit board **61B**. The first protrusion **206** may be separated from the front surface **61a** of the circuit board **61B** partly or slightly.

[0150] The second protrusion **207** is in contact with the rear surface **61b** of the circuit board **61A**. The second protrusion **207** may be further in contact with electric components **62** mounted on the rear surface **61b** of the circuit board **61A**. The second protrusion **207** may be separated from the rear surface **61b** of the circuit board **61A** partly or slightly.

[0151] The circuit boards **61A** and **61B** of the board assembly **60** are located between the first protrusion **206** and the second protrusion **207**, and are held by the first protrusion **206** and the second protrusion **207**. In other words, the first protrusion **206** and the second protrusion **207** are in contact with the front surface **61a** of the circuit board **61B** and the rear surface **61b** of the circuit board **61A**, and thereby restrict the movement of the board assembly **60** in the D_j direction.

[0152] As illustrated in FIG. 13, the third wall **213** is provided with a plurality of openings **213a**. Each of the openings **213a** is an example of a second opening. Each opening **213a** is a cutout at the end of the third wall **213** in the $-D_j$ direction. Each opening **213a** may be a hole. The external connector **62c** and the external operation switch **62d** are exposed outside the housing **20** through the openings **213a** of the buffer member **201** and the first holes **37a** of the housing **20**.

[0153] As illustrated in FIGS. 14 and 15, the buffer member **201** is attached to the board assembly **60**, and is accommodated in the housing **20**. The buffer member **201** is in contact with the housing **20** and the circuit boards **61**, so as to be separable (detachable) therefrom.

[0154] The buffer member **201** is interposed between the housing **20** and each of the rear surface **61b** of the circuit board **61A**, the front surface **61a** of the circuit board **61B**, and the upper end **61c**, the lower end **61d**, the left end **61e**, and the right end **61f** of each of the circuit boards **61A** and **61B**. Consequently, the circuit boards **61** are held by the

housing 20 through the buffer member 201 at positions separated from the housing 20.

[0155] As illustrated in FIG. 14, the frame wall 205 is interposed between the housing 20 and each of the upper end 61c, the lower end 61d, the left end 61e, and the right end 61f of each of the circuit boards 61A and 61B. The frame wall 205 surrounds the circuit boards 61A and 61B, and is surrounded by the peripheral wall 32 of the front case 21.

[0156] The first wall 211 is interposed between the upper end 61c of each of the circuit boards 61A and 61B and the upper wall 35 of the front case 21. The second wall 212 is interposed between the lower end 61d of each of the circuit boards 61A and 61B and the lower wall 36 of the front case 21. Consequently, the front case 21 holds the circuit boards 61 in the Di direction such that vibration in the Di direction can be attenuated by the buffer member 201.

[0157] The third wall 213 is interposed between the left end 61e of each of the circuit boards 61A and 61B and the left wall 37 of the front case 21. The fourth wall 214 is interposed between the right end 61f of each of the circuit boards 61A and 61B and the right wall 38 of the front case 21. Consequently, the front case 21 holds the circuit boards 61 in the Y direction such that vibration in the Y direction can be attenuated by the buffer member 201.

[0158] As illustrated in FIG. 15, the first protrusion 206 is interposed between the front surface 61a of the circuit board 61B and the front wall 31 of the front case 21. The second protrusion 207 is interposed between the rear surface 61b of the circuit board 61A and the rear wall 41 of the back cover 22. Consequently, the housing 20 holds the circuit boards 61 in the Dj direction such that vibration in the Dj direction can be attenuated by the buffer member 201.

[0159] At least some of the electric components 62 mounted on the front surface 61a of the circuit board 61B and the rear surface 61b of the circuit board 61A are exposed without being covered by the buffer member 201. However, the buffer member 201 holds the board assembly 60 at a position such that the electric components 62 are separated from the housing 20. Thus, vibration of the housing 20 can be hardly transmitted to the vibration sensor 70 through the electric components 62, the circuit boards 61, and the FPC 63.

[0160] Next, an exemplary explanation will be given of part of an assembling method of the vibration detecting device 10. The assembling method of the vibration detecting device 10 is not limited to the following method, but may be performed by using another method. First, as illustrated in FIG. 13, the board assembly 60 is assembled. The FPC 63 may be assembled to the board assembly 60 later.

[0161] Then, the board assembly 60 is accommodated into the inside of the frame wall 205, accompanied by deformation of the first protrusion 206 or the second protrusion 207. Consequently, the buffer member 201 is attached to the board assembly 60.

[0162] Then, as illustrated in FIG. 14, the circuit boards 61 and the buffer member 201 are press-fitted into the first compartment R1 of the front case 21. Consequently, the buffer member 201 is interposed between the housing 20 and each of the front surface 61a of the circuit board 61B and the upper end 61c, the lower end 61d, the left end 61e, and the right end 61f of each of the circuit boards 61A and 61B.

[0163] The material of the buffer member 201 has hardness such that the buffer member 201 can be easily attached to the board assembly 60, and the buffer member 201 and the

substrate assembly 60 can be easily accommodated in the front case 21. For example, the buffer member 201 has hardness such that the buffer member 201 can be hardly peeled off from the board assembly 60 due to its own weight and/or can be hardly peeled off from the board assembly 60 when being press-fitted into the housing 20.

[0164] Then, the bottom frame 23 is attached to the front case 21. Further, the FPC 63 and the vibration sensor 70 are attached to the bottom frame 23.

[0165] Then, as illustrated in FIG. 15, the back cover 22 is attached to the front case 21. The back cover 22 is fixed to the front case 21 while pressing the second protrusion 207 against the rear surface 61b of the circuit board 61A.

[0166] In the natural uncompressed state, the thickness of the buffer member 201 is larger than a half of the difference between the width W1 of the first compartment R1 and the width W2 of each circuit board 61, which are illustrated in FIG. 14. Consequently, when the board assembly 60 and the buffer member 201 are accommodated in the first compartment R1, the buffer member 201 is compressed between the circuit boards 61 and the housing 20. Specifically, the buffer member 201 is interposed between the circuit boards 61 and the housing 20, in a compressed state. The buffer member 201 may have a non-compressible part.

[0167] The thickness Tc of the compressed buffer member 201 is, for example, about 50 to 80% of the thickness of the buffer member 201 in the natural state. The thickness Tc is not limited to this example, but is set for the buffer member 201 to have desired vibration absorbing performance.

[0168] The dimensional difference described above is not limited by the width W1 between the left wall 37 and the right wall 38 and the width W2 between the left end 61e and the right end 61f of each circuit board 61. The buffer member 201 is compressed between the rear surface 61b of the circuit board 61A and the back cover 22, between the front surface 61a of the circuit board 61B and the front wall 31, and between the peripheral wall 32 and the upper end 61c, the lower end 61d, the left end 61e, and the right end 61f of each of the circuit boards 61A and 61B.

[0169] As the buffer member 201 is elastic, the buffer member 201 can be deformed in accordance with the shape of the gap between each circuit board 61 and the housing 20. Consequently, the buffer member 201 can come into contact with each circuit board 61, each electric component 62, and the housing 20, while enlarging the contact area.

[0170] In the housing 20 the circuit boards 61 are held by the housing 20 through the buffer member 201 attached to these circuit boards 61. Specifically, the front wall 31 supports the front surface 61a of the circuit board 61B through the first protrusion 206, the peripheral wall 32 supports the upper end 61c, the lower end 61d, the left end 61e, and the right end 61f of each of the circuit boards 61A and 61B through the frame wall 205, and the rear wall 41 supports the rear surface 61b of the circuit board 61A through the second protrusion 207. Consequently, the movement of each circuit board 61 is restricted.

[0171] The buffer member 201 is in direct contact with the housing 20, each circuit board 61, and each electric component 62, without an adhesive or double-sided adhesive tape interposed therebetween. Thus, the buffer member 201 is in contact with the housing 20, each circuit board 61, and each electric component 62, so as to be separable (detachable) therefrom.

[0172] As described above, each circuit board 61 is not fixed to the housing 20 with screws, pins, a double-sided tape, adhesive, filler, or the like, but is held by the housing 20 through the buffer member 201 with spacing from the housing 20. Thus, each circuit board 61 can move relative to the housing 20 by elastic deformation of the buffer member 201.

[0173] The buffer member 201 attenuates vibration and restrains transmission of vibration, between the circuit boards 61 and the housing 20. Thus, vibration of the housing 20 can be hardly transmitted to the vibration sensor 70 through the circuit boards 61 and the FPC 63. Further, the circuit boards 61 are restrained from being vibrated due to resonance.

[0174] Then, the shield 24 is attached to the front case 21 and the bottom frame 23, and the attachment 11 is attached to the bottom frame 23. As a result, the vibration detecting device 10 is assembled.

[0175] The board assembly 60 may be taken out of the housing 20 after the vibration detecting device 10 is produced. In this case, the back cover 22 is detached from the front case 21, and the board assembly 60 is detached from the buffer member 201, accompanied by deformation of the first protrusion 206 or the second protrusion 207. Accordingly, in the vibration detecting device 10, the board assembly 60 can be detached from the housing 20, without an operation of removing the adhesive or filler.

[0176] In the vibration detecting device 10 according to the third embodiment described above, the circuit boards 61 are held by the housing 20 through the buffer member 201. That is, the buffer member 201 spreads between the housing 20 and the circuit boards 61 to be able to restrain transmission of vibration between the housing 20 and the circuit boards 61, and attenuate vibration of the circuit boards 61. Thus, the buffer member 201 serves to restrain vibration noise due to vibration of the housing 20 transmitted through the circuit boards 61 and/or resonance of the circuit boards 61 from entering the vibration sensor 70. Further, the buffer member 201 is detachable from the housing 20, so that the circuit boards 61 can be more easily detached from the housing 20 than a vibration absorbing material filled in between the circuit boards 61 and the housing 20, for example. In addition, the circuit boards 61 can be equipped with a member with a hole, such as the external connector 62c, and/or a movable member, such as the external operation switch 62d.

[0177] The buffer member 201 is detachably attached to the circuit boards 61. Consequently, the circuit boards 61 and the attached buffer member 201 can be handled as one subassembly. The circuit boards 61 with the attached buffer member 201 can be accommodated in the housing 20. This facilitates the assembly of the vibration detecting device 10.

[0178] The buffer member 201 is interposed between the housing 20 and each of the front surfaces 61a, the rear surfaces 61b, the left ends 61e, and the right ends 61f. This can restrict the circuit boards 61 from coming into contact with the housing 20, and vibration noise due to vibration of the housing 20 transmitted through the circuit boards 61 and/or resonance of the circuit boards 61 from entering the vibration sensor 70.

[0179] The buffer member 201 includes, in a unified manner, the frame wall 205 that covers the upper ends 61c, the lower ends 61d, the left ends 61e, and the right ends 61f. The frame wall 205 stands between the housing 20, and the

upper ends 61c, the lower ends 61d, the left ends 61e, and the right ends 61f. Because of this, the buffer member 201 can cover the ends of the circuit boards 61 from substantially all the directions, preventing the circuit boards 61 from coming into contact with the housing 20. This can avoid vibration noise due to vibration of the housing 20 transmitted through the circuit boards 61 and/or resonance of the circuit boards 61 from entering the vibration sensor 70. Further, since the buffer member 201 is integrated with the frame wall 205, the buffer member 201 can be easily handled during the assembly of the vibration detecting device 10.

[0180] The buffer member 201 includes the first protrusion 206 and the second protrusion 207 that protrude from the frame wall 205. The length L of the first protrusion 206 from the frame wall 205 is smaller than the length of the frame wall 205 in the Dj direction orthogonal to the front surface 61a. That is, the first protrusion 206 of a relatively short length is elastically deformable easily. Thus, the circuit boards 61 can be easily inserted into the inside of the frame wall 205 by the elastic deformation of the first protrusion 206.

[0181] The buffer member 201 contains silicone rubber. Thus, it is possible to produce, at a lower cost, the buffer member 201 serving to reduce transmission of vibration between the housing 20 and the circuit boards 61, and attenuate vibration of the circuit boards 61. Further, owing to the silicone rubber with no viscosity or less viscosity than gel, the buffer member 201 can be easily detached from the circuit boards 61. Further, the silicon rubber is higher in strength than gel, therefore, it is less likely to be damaged. Thus, the buffer member 201 is reusable.

[0182] The buffer member 201 for holding the circuit boards 61 is higher in rigidity than the sheet 80. That is, the buffer member 201 is less likely to vary in shape, and easily attachable to the circuit boards 61. Thus, the buffer member 201 can be downsized, reducing the manufacturing cost.

[0183] The buffer member 201 spreads between the circuit boards 61 and the housing 20 in a compressed state. Specifically, the distance between the circuit boards 61 and the housing 20 is smaller than the thickness of the buffer member 201 in the natural state. Thereby, the restoring force of the buffer member 201 works to hold the circuit boards 61, and restrict the circuit boards 61 from vibrating.

[0184] The housing 20 is provided with the first holes 37a, and the buffer member 201 is provided with the openings 213a. The external connector 62c is mounted on the circuit boards 61, and is exposed outside the housing 20 through one of the first holes 37a and one of the openings 213a. Consequently, the external connector 62c is usable from outside the housing 20. For example, the external connector 62c is operable or viewable from outside, and/or another component is insertable into the external connector 62.

Fourth Embodiment

[0185] Next, an explanation will be given of a fourth embodiment with reference to FIG. 16. FIG. 16 is an exemplary perspective view illustrating a board assembly 60 and a buffer member 201 according to the fourth embodiment, in an exploded manner. As illustrated in FIG. 16, the fourth embodiment differs from the third embodiment in that the buffer member 201 includes a plurality of members.

[0186] The buffer member 201 includes a front member 221 and a rear member 222. The front member 221 includes

a frame wall **205** and a first protrusion **206**. The rear member **222** includes a frame wall **205** and a second protrusion **207**. In other words, each of the front member **221** and the rear member **222** includes a first wall **211**, a second wall **212**, a third wall **213**, and a fourth wall **214**.

[**0187**] The front member **221** and the rear member **222** are set in contact with each other, and thereby form the buffer member **201**. For example, the front member **221** and the rear member **222** are fitted to each other. The front member **221** and the rear member **222** may be separated from each other.

[**0188**] As described in the fourth embodiment, the buffer member **201** may include a plurality of members. In FIG. **16**, the buffer member **201** includes the two members separable in the Dj direction, but the buffer member **201** is not limited to this example. For example, the buffer member **201** may include two members separable in the Y direction or Di direction, or may include three or more members.

[**0189**] According to at least one of the first to fourth embodiments, the circuit board is held by the housing through an elastic member. Thus, the elastic member is interposed between the housing and the circuit board, and can restrain transmission of vibration between the housing and the circuit board and attenuate vibration of the circuit board. It is thus possible to prevent vibration noise due to vibration of the housing transmitted through the circuit board and/or resonance of the circuit board from entering the vibration sensor. Further, the elastic member is detachable from the housing, so that the circuit board can be more easily detached from the housing than a vibration absorbing material filled in-between the circuit board and the housing, for example. In addition, the circuit board can be equipped with a member with a hole, such as a connector, and/or a movable member, such as a switch.

[**0190**] While certain embodiments have been described, these embodiments have been presented by way of example only, and are not intended to limit the scope of the inventions. Indeed, the novel embodiments described herein may be embodied in a variety of other forms; furthermore, various omissions, substitutions and changes in the form of the embodiments described herein may be made without departing from the spirit of the inventions. The accompanying claims and their equivalents are intended to cover such forms or modifications as would fall within the scope and spirit of the inventions.

What is claimed is:

1. A vibration detecting device comprising:
 - a housing;
 - a vibration sensor accommodated in the housing;
 - a circuit board accommodated in the housing and equipped with a first electric component, the first electric component configured to process a detection signal of the vibration sensor;
 - a flexible wiring member that electrically connects the vibration sensor and the circuit board to each other; and
 - an elastic member containing a polymer material, and accommodated in the housing in contact with the housing and the circuit board, and being detachable from the housing,
 wherein the circuit board is held by the housing through the elastic member.
2. The vibration detecting device according to claim 1, wherein

the elastic member is detachably attached to the circuit board.

3. The vibration detecting device according to claim 1, wherein

the circuit board includes:

- a first surface,
- a second surface opposite to the first surface,
- a first end in a first direction along the first surface, and
- a second end in a second direction opposite to the first direction, and

the elastic member is interposed between the housing and each of the first surface, the second surface, the first end, and the second end.

4. The vibration detecting device according to claim 3, wherein

the circuit board includes:

- a third end in a third direction orthogonal to the first direction along the first surface, and
- a fourth end in a fourth direction opposite to the third direction,

the elastic member includes a frame wall in a unified manner, the frame wall that covers the first end, the second end, the third end, and the fourth end, and the frame wall is interposed between the housing and each of the first end, the second end, the third end, and the fourth end.

5. The vibration detecting device according to claim 4, wherein

the elastic member includes:

- a first protrusion that protrudes from the frame wall and is interposed between the first surface and the housing, and
- a second protrusion that protrudes from the frame wall and is interposed between the second surface and the housing, and

the first protrusion from the frame wall is smaller in length than the frame wall in a direction orthogonal to the first surface.

6. The vibration detecting device according to claim 5, wherein

the circuit board includes a first board and a second board electrically connected to the first board,

the first board includes the first surface, a third surface opposite to the first surface, the first end, the second end, the third end, and the fourth end, and

the second board includes the second surface and a fourth surface facing the third surface.

7. The vibration detecting device according to claim 6, wherein

the second board includes:

- a fifth end in the first direction,
- a sixth end in the second direction,
- a seventh end in the third direction, and
- an eighth end in the fourth direction,

the second board is separated from the first board, and the frame wall is interposed between the housing and each of the fifth end, the sixth end, the seventh end, and the eighth end, and covers a space between the first board and the second board.

8. The vibration detecting device according to claim 7, wherein

the elastic member comprises a first member including the first protrusion, and a second member including the second protrusion, and

the frame wall includes a first frame wall of the first member, and a second frame wall of the second member.

9. The vibration detecting device according to claim **5**, further comprising

a connector that is mounted on the first surface with spacing from the frame wall and the first protrusion, and is exposed outside the elastic member, wherein the wiring member is electrically connected to the circuit board through the connector.

10. The vibration detecting device according to claim **1**, wherein the elastic member contains silicone rubber.

11. The vibration detecting device according to claim **1**, wherein

the elastic member comprises a flexible sheet, and the circuit board is held by the housing through the sheet.

12. The vibration detecting device according to claim **11**, wherein the sheet is formed of a gel.

13. The vibration detecting device according to claim **12**, wherein the sheet is formed of α GEL (registered trademark).

14. The vibration detecting device according to claim **11**, wherein

the circuit board includes a first surface, a second surface opposite to the first surface, a first end in a first direction along the first surface, and a second end in a second direction opposite to the first direction, and the sheet is bent to wrap around the circuit board, and is interposed between the housing and each of the first surface, the second surface, the first end, and the second end.

15. The vibration detecting device according to claim **11**, wherein

the housing comprises a box member and a lid member, the box member includes an inner surface facing the circuit board, and a peripheral wall that protrudes from the inner surface and surrounds the circuit board, and

the lid member is attached to an end of the peripheral wall such that the lid member closes an inside of the box member and presses part of the sheet against the circuit board.

16. The vibration detecting device according to claim **15**, wherein

the sheet includes a surface facing the circuit board, and an edge in a direction along the surface, and the edge is located between the circuit board and the lid member.

17. The vibration detecting device according to claim **11**, wherein

the sheet includes mutually directly contacting, overlapping portions, and is in direct contact with the housing and the circuit board.

18. The vibration detecting device according to claim **1**, wherein

the elastic member is interposed between the circuit board and the housing in a compressed state.

19. The vibration detecting device according to claim **1**, wherein

the housing is provided with a first opening, the elastic member is provided with a second opening, and the circuit board is equipped with a second electric component that is exposed outside the housing through the first opening and the second opening.

20. The vibration detecting device according to claim **1**, wherein

the housing is provided with a hole, the circuit board has a light emitting component mounted thereon, and the elastic member covers the light emitting component, and allows light to pass through.

* * * * *